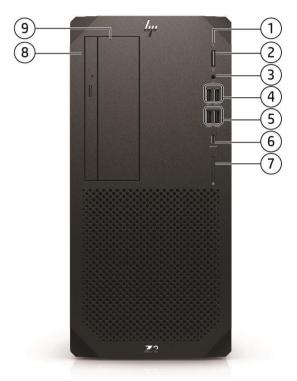
Overview

HP Z2 G9 Tower Workstation Desktop PC



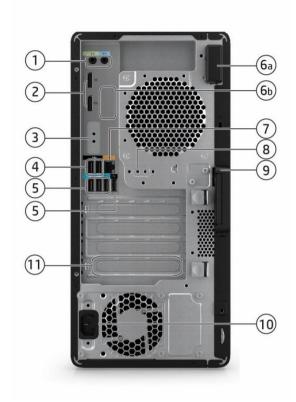
front

- 1. HDD Activity LED
- 2. Power button
- 3. Universal audio jack (with CTIA & OMTP headset support)
- 4. (2) USB-A 10Gbps ports (1 charge port supports up to 5V/2.1A)
- 5. (2) USB-A 10Gbps rate ports

- 6. (1) USB-C® 20Gbps port (optional, charge supports up to 5V/3A)
- 7. SD card reader 4.0 (optional)
- 8. Slim ODD bay
- 9. External 5.25" bay



Overview



rear

- 1. (1) Audio Line-in jack
 - (1) Audio Line-out jack
- (2) DisplayPort 1.4 ports
- 3. Flex I/O module: choose one from the following: (1) DisplayPort 1.4, (1) HDMI 2.0b, (1) VGA, (1) Dual USB-A 5Gbps port, (1) USB-C® 10Gbps port (Power Delivery 15W, Alt Mode DisplayPort), (1) 2nd 1 GbE LAN, (1) Thunderbolt 3 with USB-C® / USB4 40Gbps * (cabled to PCIe AIC**) (1) 1Gbps Fiber LC NIC
- 4. (2) Hi-Speed USB-A 480Mbps port
- 5. (2) USB-A 10Gbps ports
 - (1) USB-A 5Gbps port
 - (1) Hi-Speed USB-A 480Mbps port
- *Maximum speed requires DisplayPort™ and PCIe aggregation.
- **Thunderbolt support only in PCI-E slot4.

NOTE: Onboard Display support DP1.4/HBR2. Flex I/O module Display support DP1.4/HBR3. Resolution all support up to 5120x3200 24bpp @60Hz.

Form Factor

Tower

Operating Systems

Preinstalled:

- Windows 11 Pro HP recommends Windows 11 Pro²
- Windows 11 Home HP recommends Windows 11 Pro²
- Windows 10 Pro (available through downgrade rights from Windows 11 Pro) 1,2,3
- Linux®-ready⁵

- - 6. (1) WLAN Antenna (optional)
 - a. Internal
 - b. External
 - 7. (1) 1Gb LAN
 - 2nd serial port (optional) 8.
 - Hood lock (optional) 9.
 - 10. Power connector

Overview

- Ubuntu^{®4,5}
 - Intel 12th generation processors will support and preinstall Ubuntu 20.02 and 20.04.
 - Intel 13th generation processors support and preinstall Ubuntu 22.04 LTS

Web-supported only:

Windows 10 Enterprise 64²

Supported Version:

- HP tested Windows 10, versions 20H2, 21H1, 21H2 and 22H2 on this platform. For testing
 information on newer versions of Windows 10, please see:
 https://support.hp.com/document/c05195282.
- Red Hat® Enterprise Linux® Workstation 86
- SUSE Linux® Enterprise Desktop 156
- Ubuntu^{®4,5}
 - Intel 12th generation processors will support and preinstall Ubuntu 20.02 and 20.04.
 - Intel 13th generation processors support and preinstall Ubuntu 22.04 LTS
- ¹ Device comes with Windows 10 and a free Windows 11 upgrade or may be preloaded with Windows 11. Upgrade timing may vary by device. Features and app availability may vary by region. Certain features require specific hardware (see Windows 11 Specifications).
- ² Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows is automatically updated and enabled. High speed internet and Microsoft account required. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com.
- ³This system is preinstalled with Windows 10 Pro software and also comes with a license for Windows 11 Pro software and provision for recovery software. You may only use one version of the Windows software at a time. Switching between versions will require you to uninstall one version and install the other version. You must back up all data (files, photos, etc.) before uninstalling and installing operating systems to avoid loss of your data.
- ⁴ Not all features are available in all editions or versions of Ubuntu. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS to take full advantage of Ubuntu functionality. Ubuntu may be automatically updated. ISP fees may apply and additional requirements may apply over time for updates.
- ⁵A certified preloaded version of Ubuntu® 20.04 LTS is available from HP for this platform. Not all features are available in all editions or versions of Ubuntu. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS to take full advantage of Ubuntu functionality. Ubuntu may be automatically updated. ISP fees may apply, and additional requirements may apply over time for upgrades.

⁶For detailed Linux[®] OS/hardware support information, see: http://www.hp.com/support/linux_hardware_matrix

NOTE: Your product does not support Windows 8 or Windows 7. In accordance with Microsoft's support policy, HP does not support the Windows® 8 or Windows 7 operating system on products configured with Intel® and AMD® 7th generation and forward processors or provide any Windows® 8 or Windows 7 drivers on http://www.support.hp.com. A full list of HP products and the Windows 10 versions tested is available on the HP support website. https://support.hp.com/us-en/document/c05195282

Processors Overview 1,2,3,4,5

Intel 13th Generation Processors:

Intel® Core™ i5-13400 (2.5GHz P-Core base frequency, 1.8GHz E-Core base frequency, up to 3.3GHz E-Core Max Turbo frequency, up to 4.6 GHz P-core Max Turbo frequency, 20MB L3 cache, 6 P-cores and 4 E-cores, 16 threads)



Overview

Intel® Core™ i5-13500 (2.5GHz P-Core base frequency, 1.8GHz E-Core base frequency, up to 3.5GHz E-Core Max Turbo frequency, up to 4.8 GHz P-core Max Turbo frequency, 24MB L3 cache, 6 P-cores and 8 E-cores, 20 threads)

Intel® Core™ i5-13600 (2.7GHz P-Core base frequency, 2GHz E-Core base frequency, up to 3.7GHz E-Core Max Turbo frequency, up to 5 GHz P-core Max Turbo frequency, 24MB L3 cache, 6 P-cores and 8 E-cores, 20 threads)

Intel® Core™ i5-13600K (3.5GHz P-Core base frequency, 2.6GHz E-Core base frequency, up to 3.9GHz E-Core Max Turbo frequency, up to 5.1 GHz P-core Max Turbo frequency, 24MB L3 cache, 6 P-cores and 8 E-cores, 20 threads)

Intel® Core™ i7-13700 (2.1GHz P-Core base frequency, 1.5GHz E-Core base frequency, up to 4.1Ghz E-Core base frequency, up to 5.1Ghz E-Core base frequency, 30MB L3 cache, 8 P-cores and 8 E-cores, 24 threads)

Intel® Core™ i7-13700K (3.4GHz P-Core base frequency, 2.5GHz E-Core base frequency, up to 4.2GHz E-Core Max Turbo frequency, up to 5.3 GHz P-core Max Turbo frequency, 30MB L3 cache, 8 P-cores and 8 E-cores, 24 threads)

Intel® Core™ i9-13900 (2GHz P-Core base frequency, 1.5GHz E-Core base frequency, up to 4.2GHz E-Core Max Turbo frequency, up to 5.2 GHz P-core Max Turbo frequency, 36MB L3 cache, 8 P-cores and 16 E-cores, 32 threads)

Intel® Core™ i9-13900K (3GHz P-Core base frequency, 2.2GHz E-Core base frequency, up to 4.3GHz E-Core Max Turbo frequency, up to 5.4 GHz P-core Max Turbo frequency, 36MB L3 cache, 8 P-cores and 16 E-cores, 32 threads)

Intel 12th Generation Processors:

Intel® Core™ i9-12900K (2.4GHz E-core base frequency, 3.2GHz P-core base frequency, up to 3.9 GHz E-core Max Turbo frequency, up to 5.1 GHz P-core Max Turbo frequency, 30MB L3 cache, 8 P-cores and 8 E-cores, 24 threads)

Intel® Core™ i9-12900 (1.8GHz E-core base frequency, 5.0 GHz P-core base frequency, up to 3.8 GHz E-core Max Turbo frequency, up to 5.0 GHz P-core Max Turbo frequency, 30MB L3 cache, 8 P-cores and 8 E-cores, 24 threads)

Intel® Core™ i7-12700K (2.7 GHz E-core base frequency, 3.6 GHz P-core base frequency, up to 3.8 GHz E-core Max Turbo frequency, up to 4.9 GHz P-core Max Turbo frequency, 25MB L3 cache, 8 P-cores and 4 E-cores, 20 threads)

Intel® Core™ i7-12700 (1.6 GHz E-core base frequency, 2.1 GHz P-core base frequency, up to 3.6 GHz E-core Max Turbo frequency, up to 4.8 GHz P-core Max Turbo frequency, 25MB L3 cache, 8 P-cores and 4 E-cores, 20 threads)

Intel® Core™ i5-12600K (2.8 GHz E-core base frequency, 3.7 GHz P-core base frequency, up to 3.6 GHz E-core Max Turbo frequency, up to 4.9 GHz P-core Max Turbo frequency, 20MB L3 cache, 6 P-cores and 4 E-cores, 16 threads)

Intel® Core™ i5-12600 (3.3 GHz P-core base frequency, up to 4.8 GHz P-core Max Turbo frequency, 18MB L3 cache, 6 P-cores and 0 E-cores, 12 threads)

Intel® Core™ i5-12500 (3.0 GHz P-core base frequency, up to 4.6 GHz P-core Max Turbo frequency, 18MB L3 cache, 6 P-cores and 0-E-cores, 12 threads)

Intel® Core™ i5-12400 (2.5 GHz P-core base frequency, up to 4.4 GHz P-core Max Turbo frequency, 18MB L3 cache, 6 P-cores and 0-E cores. 12 threads)

Intel® Core™ i3-12300 (3.5 GHz P-core base frequency, up to 4.4 GHz P-core Max Turbo frequency, 12MB, 4 P-cores. 8 threads)

Intel® Core™ i3-12100 (3.3 GHz P-core base frequency, up to 4.3 GHz P-core Max Turbo frequency, 12MB, 4 P-cores. 8 threads)

¹ Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.

² Intel® Optane™ memory system acceleration does not replace or increase the DRAM in your system.

³ Intel Turbo Boost performance varies depending on hardware, software and overall system configuration. See http://www.intel.com/technology/turboboost for more information.

⁴ Intel vPro® requires Windows 10 Pro 64 bit or higher, a vPro supported processor, vPro enabled chipset, vPro enabled wired LAN and/or Wi-Fi 6E WLAN and TPM 2.0. Some functionality requires additional 3rd party software in order to run. Features of vPro® Essentials and Enterprise vary. See http://intel.com/vpro



Overview

⁵ Memory will run at 4400 speed (MT/s) in 2DPC within 1DIMM population; memory will run at 4000 speed (MT/s) in 2DPC within 2DIMM of 1 Rank population and memory will run at 3600 speed (MT/s) in 2DPC within 2DIMM of 2 Rank population

Color Black Convertibility No

Expansion Slots (see Slot 1: PCIe Gen5 x16

system board section for Slot 2: PCle Gen3 x1 - with x4 open end Connector

more details)

Slot 4: PCIe Gen3 x4 with open end connector

Slot 3: PCIe Gen3 x4 - with x16 Connector

Expansion Bays (see (2) Internal 3.5" bays

storage section for more (1) External 5.25" bay

details)

(1) Internal 2.5" bay (for SSD only)

(1) Dedicated 9.5mm slim optical disk drive bay

Front I/O (2) USB-A 10Gbps ports (1 charge port supports up to 5V/2.1A), (2) USB-A 10Gbps ports, (1) USB-C

20Gbps eport (charge supports up to 5V/3A, optional), (1) SD card reader (optional), (1) universal audio

iack

Internal I/O [5] (1) Hi-Speed USB 480Mbps header for SD card reader

> (1) serial port available with header (1) serial and PS/2 available with header

Rear I/O (2) DisplayPort 1.4 ports, (1) Audio Line out, (1) Audio Line in, (1) 1GbE LAN, (3) Hi-Speed USB 480Mbps

ports. (2) USB-A 10Gbps ports. (1) USB-A 5Gbps port. (1) serial (optional). (1) Flex I/O port (VGA, HDMI 2.0b, DisplayPort 1.4, USB-C® 10Gbps port (Power Delivery 15W, Alt Mode Display Port), (1) Dual USB-A 5Gbps port. (1) 2nd 1GbE LAN. (1) Thunderbolt 3 with USB4 USB-C® 40Gbps (cabled to PCIe AIC)*. (1)

1Gbps Fiber LC NIC

Optional I/O Flex IO* – choose one of the following options: (1) DisplayPort™ 1.4 port, (1) HDMI 2.0b, (1) VGA,(1) 2nd

1GbE LAN. (1) 1Gbps Fiber LC NIC, (1) Dual USB-A 5Gbpsport (1) USB -C® 10Gbps port (15W USB Power Delivery, Alt Mode DisplayPort™), (1) Thunderbolt™ 3 with USB4 USB-C® 40Gbps port (cabled to PCIe®

AIC**);

Front – (1) USB-C[®] 20Gbps port (charging), (1) SD card reader;

Front – choose one of the following options: (1) USB-C @ 20Gbps (charging), (1) SD 4.0 card reader

Rear -(1) serial:

*About Thunderbolt compatibility, please refer to the FAO of Thunderbolt community.

https://www.thunderbolttechnology.net/tech/fag

**Flex IO port and PCIe slot 4 will be occupied when Thunderbolt is installed.

Interfaces Supported SD card reader (optional)

On-board RAID Support SATA and NVME RAID 0 Striped Array

SATA RAID and NVME RAID 1 Mirror Array

Chassis Dimensions (H x H: 14" [356mm]

W: 6.7" [169mm] WxD)

D: 15.2" [385mm]



Overview

Packaged Dimensions H: 20.39" (518mm)

> W: 11.61" (295mm) D: 19.29" (490mm)

Rack Dimensions

Weight Exact weights depend upon configuration (System weight only).

Starting at 6.2kg (13.7lbs.)

Operating: 5° to 35° C (40° to 95° F) **Temperature**

Above 1524 m (5,000 feet) altitude, the maximum operating temperature is reduced by 1° C (1.8° F) for

every 305 m (1.000 feet) increase in elevation Non-operating: -40° to 60° C (-40° to 140° F)

Maximum rate of change: 10°C/hr

Humidity Operating: 10% to 85% RH, non-condensing, 35° C maximum wet bulb

Non-operating: 10% to 90% RH, non-condensing, 35° C maximum wet bulb

pressurized)6

Maximum Altitude (non- Operating (with Rotational Hard Drives): 3,048 m (10,000 feet) Operating (with only Solid-State Drives): 5,000 m (16,404 feet)

Non-operating: 12,192 m (40,000 feet)

Maximum operating temperature is reduced as altitude increases. See

Temperature for details.

700W wide-ranging, active Power Factor Correction, 92% Efficiency with two 6+2 graphics power **Power Supply**

> connectors. 500W wide-ranging, active Power Factor Correction, 90% Efficiency. 450W wide-ranging, active Power Factor Correction, 90% Efficiency, 350W wide-ranging, active Power Factor Correction,

92% Efficiency.

NOTE: The Power Supply Efficiency Report for the 700W 92% Efficiency, 500W 90% Efficiency, 450W

90% Efficiency and 350W 92% Efficiency Power Supply may be found at the following links:

700W PSU:

https://www.plugloadsolutions.com/80PlusPowerSuppliesDetail.aspx?id=0&type=2

500W PSU:

LiteOn 500W PSU Efficiency Report **Delta 500W PSU Efficiency Report**

450W PSU:

https://www.plugloadsolutions.com/80PlusPowerSuppliesDetail.aspx?id=0&type=2

350W PSU:

AcBel 350W PSU (SFF) Efficiency Report AcBel 350W PSU (Custom) Efficiency Report

Delta 350W PSU Efficiency Report

For a complete listing of compatible DAT tape drives, LTO tape drives and RDX Removable Disk Backup **Backup Devices**

System offerings, please visit http://www.hp.com/go/connect

Chipset Intel® W680 chipset

4 DIMM slots, supporting up to 128GB ECC/non-ECC, DDR5 4800 MT/s speed depending on the system Memory

configuration

Supported Components

SATA Hard Drives		Factory Configured	Option Kit	Option Kit Part Number
	500GB SATA 7200 rpm 6Gb/s 3.5" HDD	Υ	Υ	LQ036AA
	1TB SATA 7200 rpm 6Gb/s 3.5" HDD	Υ	Υ	LQ037AA
	2TB SATA 7200 rpm 6Gb/s 3.5" HDD	Υ	Υ	QB576AA
	1TB SATA 7200 rpm 6Gb/s 3.5" HDD (Enterprise Class)	Υ	Υ	WOR10AA
	2TB SATA 7200 rpm 6Gb/s 3.5" HDD (Enterprise Class)	Υ	Υ	2Z274AA
	4TB SATA 7200 rpm 6Gb/s 3.5" HDD (Enterprise Class)	Υ	Υ	K4T76AA
	8TB SATA 7200 rpm 6Gb/s 3.5" HDD (Enterprise Class)	Υ	Υ	2Z273AA
	12TB SATA 7200 rpm 6Gb/s 3.5" HDD (Enterprise Class)	Υ	Υ	5S461AA
	500GB SATA 7.2K SED HDD	Υ	Υ	D8N29AA

NOTE: For internal bay install, HDD option kits require separate purchase of 6Z9U6AA HP Z2 Tower HDD Cable Kit. For external bay install, HDD options kits require separate purchase of 6Z9U6AA HP Z2 Tower HDD Cable Kit & NQ099AA HP Optical Bay HDD Mounting Bracket.

PCIe Solid State Drives

HP ZTurbo 512GB PCIe-Gen 4x4 TLC Z2 SSDKit	Υ	Υ	201G0AA/AT
HP ZTurbo 512GB PCIe-Gen 4x4 SED Z2 SSDKit	Υ	Υ	201F9AA
HP ZTurbo 1TB PCIe-Gen 4x4 TLC Z2 SSDKit	Υ	Υ	201F5AA/AT
HP ZTurbo 2TB PCIe-Gen 4x4 TLC Z2 SSDKit	Υ	Υ	201F8AA
Z Turbo 1TB 2280 PCIe-Gen4x4 Self Encrypted OPAL2 TLC M.2 Z2 SSD	Υ	Υ	223A3AA/AT
Z Turbo 2TB 2280 PCIe-Gen4x4 Self Encrypted OPAL2 TLC M.2 Z2 SSD	Υ	Υ	223A4AA/AT
256GB 2280 PCIe-4x4 NVMe Value M.2 Z2 Kit SSD	Υ	Υ	4M9Z1AA
512GB 2280 PCIe-4x4 NVMe Value M.2 Z2 Kit SSD	Υ	Υ	4M9Z2AA
1TB 2280 PCIe-4x4 NVMe Value M.2 Z2 Kit SSD	Υ	Υ	4M9Z3AA
Z Turbo 4TB 2280 PCIe-4x4 TLC M.2 Z2 Kit SSD	Υ	Υ	5S492AA
Z Turbo 2TB PCIe-4x4 TLC SSD Module	Υ	Υ	38T75AA
Z Turbo 1TB 2280 PCIe-4x4 SED OPAL2 TLC M.2 SSD Module	Υ	Υ	38T76AA
Z Turbo 1TB PCIe-4x4 TLC SSD Module	Υ	Υ	38T77AA
Z Turbo 2TB 2280 PCIe-4x4 SED OPAL2 TLC M.2 SSD Module	Υ	Υ	38T79AA
Z Turbo 512GB PCIe-4x4 TLC SSD Module	Υ	Υ	38T80AA
Z Turbo 512GB 2280 PCIe-4x4 SED OPAL2 TLC M.2 SSD Module	Υ	Υ	38T81AA
Z Turbo 4TB 2280 PCIe-4x4 TLC M.2 SSD Module	Υ	Υ	5S496AA
Z Turbo 4TB 2280 PCIe-4x4 SED OPAL2 TLC M.2 SSD Module	Υ	Υ	5S497AA
Z Turbo 4TB 2280 PCIe-4x4 SED OPAL2 TLC M.2 Z2 Kit SSD	Υ	Υ	5S498AA
NAME OF A STREET O			

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

Graphics Option Kit

Factory Part Supported Support Configured Option Kit Number # of cards Notes



Supported Components

Granhics Cable Adanters	HP DisplayPort To HDMI True 4k Adapter	Υ	Y	2JA63AA		
Grapines caste naapters	HP Single miniDP-to-DP Adapter Cable	Y	Y	2MY05AA		
	HP DisplayPort To DVI-D Adapter	Y	Y	FH973AA		
	HP DisplayPort To DVI Adapter (Bulk 90)	Υ	Y	FH973A6		
	in bisplayi ore to by maple: (balk 50)	•	Y	AS615AA/		
	HP DisplayPort To VGA Adapter	Υ	•	AT		
	HP DisplayPort to VGA Adapter Bulk		Υ			
	Qty.90)	Υ		AS615A6		
	HP DisplayPort To VGA Adapter	Υ	Υ	F7W97AA		
	HP USB-C to DisplayPort Adapter	Υ	Υ	4SH08AA		
	HP USB-C to HDMI Adapter	Υ	Υ	4SH07AA		
	HP USB-C to VGA Adapter	Υ	Υ	4SH06AA		
Entry 3D	NVIDIA® T400 4 GB Graphics ²	Υ	Υ	5Z7EOAA/ AT	2	1
	NVIDIA® T600 4 GB Graphics ¹	N	Υ	340K9AA	2	1
	AMD Radeon Pro WX 3200 4GB	Υ	Υ	6YT6*AA/ AT	1	1
	AMD Radeon RX 6400 4 GB DH DP+HDMI Graphics	N	Υ	6Q3U4AA/ AT	1	1
Mid-range 3D	NVIDIA® T1000 4 GB Graphics	Υ	Υ		2	1
	NVIDIA® T1000 8 GB Graphics	Υ	Υ	5Z7D8AA/ AT	2	1
	NVIDIA Long-Life T1000E 8 GB 4mDP Graphics	Υ	Υ	6V9V4AA/ AT	2	1
	NVIDIA RTX™ A2000 6 GB 4mDP Graphics*	Υ	Υ	340L0AA	2	
	NVIDIA RTX™ A2000 12GB Graphics*	Υ	Υ	5Z7D9AA/ AT	2	
	NVIDIA RTX™ A4000 16GB*	Υ		20X24AA/ AT	2	
	NVIDIA Long-Life RTX A4000E 16 GB 4DP Graphics*	Υ	Υ	6Н7Ј7АА	1	
	NVIDIA Long-Life RTX A2000E 12 GB 4mDP Graphics	Υ	Υ	6V9V5AA/ AT	2	
	AMD Radeon™ Pro W6600 Graphics (8GB GDDR6 dedicated) *	Υ	Υ	340K5AA	1	
High-End 3D	AMD Radeon™ Pro W6800 Graphics (32 GB GDDR6 dedicated) *	Υ	Υ	340K7AA	1	
	AMD Radeon Pro W7900 48 GB 3DP+1mDP Graphics	Υ	Υ	8F699AA	1	
	NVIDIA® RTX™ A5000 24 GB Graphics*	Υ	Υ	20X23AA/ AT	1	
	NVIDIA RTX 5000 Ada 32 GB 4DP Graphics	Υ	Υ	8D6B6AA	1	
	AMD Radeon™ RX 6700 XT 12GB*	Υ	Υ	4C2O3AA	1	
	NOTE: 72 G9 Tower with 700W PSU can sup	ה חד חוו to a	250W prof	essional graphi	rs card fro	m HP 👵

NOTE: Z2 G9 Tower with 700W PSU can support up to a 250W professional graphics card from HP, either factory-configured or added via after-market option, and can support up to 320W total graphics power when graphics is factory-configured.



Supported Components

Note 1: When dual graphics is configured the 450W and 500W base units will require the AMO HP Z2 TWR Dual Front Fan Kit part number 4N007AA; One storage device configuration for higher than 75W graphics cards (T1000 and up)

^{*} Requires 700W chassis.

Memory		Factory Configured	Option Kit	Option Kit Part Number	Support Notes
	HP 8GB (1x8GB) DDR5-4800 nECC UDIMM	Υ	Υ	4M9X9AA	
	HP 16GB (1x16GB) DDR5-4800 nECC UDIMM	Υ	Υ	4M9Y0AA	
	HP 16GB (1x16GB) DDR5-4800 ECC UDIMM	Υ	Υ	4M9Y1AA	1
	HP 32GB (1x32GB) DDR5-4800 nECC UDIMM	Υ	Υ	4M9Y2AA	
	HP 32GB (1x32GB) DDR5-4800 FCC LIDIMM	γ	Υ	4Μ9Υ3ΔΔ	1

NOTE 1: ECC memory is supported

GENERAL NOTE: Two channels of DDR5 memory are supported. To realize full performance at least one DIMM must be inserted into each channel.

Though the memory modules can run up to 4800MHz, the current platform will support maximum memory speed of 4400MHz.

The system speed will be determined by a number of key factors:

Module Configuration	Description of configuration	Max Memory Speed (Actual Memory speed is dependent on CPU)
Single DIMM per channel	Configurations that contain only one or two DIMM modules with DIMMs only in the black slots	4400MHz
Two single ranked DIMMs in a channel	Configurations with 3 or 4 single ranked DIMMs (8GB and 16GB) installed in a system	4000MHz
Two dual ranked DIMMs in a channel	Configurations with 3 or 4 dual ranked DIMMs (32GB) installed in a system	3600MHz

When more than one memory slot is populated, symmetric configurations are required for 2 DIMMs per channel. Mix of different part numbers or mix of single and dual ranks within a channel is not allowed.

Optical and Removable Storage		Factory Configured	Option Kit	Option Kit Part Number
	HP DX175 Removable HDD Frame/Carrier	Υ	Υ	1ZX71AA
	HP DX175 Removable HDD Spare Carrier	Υ	Υ	1ZX72AA
	HP Z2 TWR SuperMulti DVD-Writer 9.5mm Slim ODD	Υ	Υ	4L5K0AA
	HP Z2 TWR DVD-ROM 9.5mm Slim ODD	Υ	Υ	4L5K1AA
	HP CRU QX328 5.25 in Front Removable M.2 Frame/Carrier	Υ	Υ	4N011AA
	HP CRU Secure High Performance Storage Module with 2TB M.2 SSD	Υ	Υ	56Q87AA
	HP CRU Secure High Performance Storage Module with 1TB M.2 SSD	Υ	Υ	56Q88AA
	HP CRU Secure High Performance Storage Module with 512GB M.2 SSD	Υ	Υ	56Q89AA



Supported Components

HP CRU SHIPS M.2 Spare Carrier

Y Y 633X9AA

NOTES: Duplication of copyrighted material is strictly prohibited. Actual speeds may vary. Double Layer media compatibility will widely vary with some home DVD players and DVD-ROM drives. Note that DVD-RAM cannot read or write to 2.6GB Single Sided/5.2 Double Sided-Version 1.0 Media.

4NO11AA HP CRU QX328 5.25in Front Removeable Frame/Carrier requires a separate purchase of HP CRU SHIPS Storage Module(s).

HP CRU Secure High Performance Storage (SHIPS) Module Kit contains select M.2 SSD for install into a factory configured or after market option front removeable storage carrier (HP CRU QX328 Frame/Carrier).

Networking and Communications	Factory Configured	Option Kit	Option Kit Part Number
Integrated Intel® I219LM PCIe GbE Controller (Intel® vPro® with Intel® AMT 16.0)	Υ	N	
HP 1GbE LAN Flex Port 2020	Υ	Υ	141J6AA/AT
HP Flex 1GbE Fiber LC Single Port	Υ	Υ	20J15AA
NVIDIA Mellanox ConnectX-6 DX Dual Port 10/25GbE SFP28 NIC ¹	Υ	Υ	436M8AA
HP 10GbE SFP+ SR/SW LC Fiber Optic Transceiver	Υ	Υ	860T8AA
HP 25GbE SFP28 LC Fiber Optic Transceiver	Υ	Υ	860T9AA
Intel Ethernet I350-T4 4-Port 1Gb NIC*	N	Υ	W8X25AA
Intel X550 10GBASE-T Dual Port NIC	Υ	Υ	1QL46AA
Intel Ethernet Network Adapter I225-T1	Υ	Υ	406L9AA
Intel Wi-Fi 6E AX211 BT 5.3 wireless card M.2 non-vPro1,**,***	Υ	N	

^{*}Intel I350-T4 4-port GbE NIC is an After Market Option only.

Allied Telesis AT-2911T/2-901 Dual Port 1GbE NIC

Υ

NOTES:

The integrated network connection is required to support Intel® vPro® Technology.

If AMT is provisioned, then network teaming with the integrated LAN port is not possible.

"Gigabit" Ethernet indicates compliance with IEEE standard 802.3ab for Gigabit Ethernet, and does not connote actual operating speed of 1 Gb/sec. For high-speed transmission, connection to a Gigabit Ethernet server and network infrastructure is required.



6E3Y9AA/AT

¹ Intel AX211 with Internal antenna support WIFI 6/WIFI 6E

^{**}Wi-Fi 6E requires a Wi-Fi 6E router, sold separately, to function in the 6GHz band. Availability of public wireless access points limited. Wi-Fi 6E is backwards compatible with prior 802.11 specs. And available in countries where Wi-Fi 6E is supported.

^{***}Intel AX211 must be configured at time of purchase. Not available as an After Market Option.

Supported Components

Input Devices		Factory Configured	Option Kit	Option Kit Part Number
	HP USB 320K Keyboard	Y	Υ	9SR37AA
	HP 320M Wired Mouse	Υ	Υ	9VA80AA
	HP Wired Desktop 320MK Mouse and Keyboard	N	Υ	9SR36AA
	HP 125 Wired Keyboard	Υ	Υ	266C9AA
	HyperX Alloy MKW100 - Mechanical Gaming Keyboard	N	Υ	4P5E1AA
	HP 975 USB+BT Dual Mode Wireless	N	Υ	3Z726AA
	HP 655 Wireless USB BLK KBD/MSE Kit	N	Υ	N/A
	HP 125 Wired Mouse	Υ	Υ	265A9AA
	HP 128 Laser Wired Mouse	Υ	Υ	265D9AA
	HP 935 Creator Wireless Mouse	N	Υ	1DOK8AA
	HyperX Pulsefire Haste Black Wireless Gaming Mouse 2	N	Υ	6N0B0AA
	HyperX Pulsefire Haste White Wireless Gaming Mouse 2	N	Υ	6NOA9AA
	HyperX Pulsefire Core - Gaming Mouse	N	Υ	4P4F8AA
	HP 455 Programmable Wireless Keyboard	Υ	Υ	4R177AA
	HP 455 Programmable Wireless Keyboard (Bulk Qty.12)	Υ	Υ	4R177A6
	HP 655 Wireless Keyboard and Mouse Combo	Υ	Υ	4R009AA
	HP 655 Wireless Keyboard and Mouse Combo (Blk Qty.10)	Υ	Υ	4R009A6
	HyperX Cloud MIX Wireless GAM HEADSET	N	Υ	4P5K9AA
	HyperX Cloud Core BLK GAM HEADSET	N	Υ	4P4F2AA
	HyperX Cloud Flight - Wireless Gaming Headset (Black-Red) (HX-HSCF-BK/AM)	N	Υ	4P5L4AA
	HyperX Cloud Stinger Core GAM HEADSET PC	N	Υ	4P4F4AA
	HyperX SoloCast - USB Microphone (Black) (HMIS1X-XX-BK/G)	N	Υ	4P5P8AA
	NOTE: Keyboard and Mouse are optional or add on features.			
Flex Module (Rear IO)		Factory Configured	Option Kit	Option Kit Part Number
	HP 1GbE LAN Flex Port 2020	Υ	Υ	141J6AA/AT
	HP DP Flex Port 2020	Υ	Υ	141J7AA/AT
	HP Dual USB-A 3.2 Gen1 Flex Port 2020	Υ	Υ	141J8AA/AT
	HP HDMI Flex Port	Υ	Υ	69D47AA/AT
	HP USB-C 3.2 Gen2 Alt Flex Port 2020	Υ	Υ	141K6AA/AT
	HP VGA Flex Port 2020	Υ	Υ	141K7AA/AT
	HP Flex 1GbE Fiber LC Single Port	Υ	Υ	20J15AA
Other Hardware		Factory Configured	Option Kit	Option Kit Part Number
	HP Single TBT3 wType C and USB4 PCIe x4 Card	Υ	N	N/A
	HP Z2 Internal Serial Port and PS/2 Port	Υ	Υ	141K9AA/AT
	HP Z2 Power Cord Kit	Υ	Υ	1N1D5AA
	HP Z2 2nd serial port adapter	Υ	Υ	141K8AA/AT



HP Z2 Tower Dust Filter

Υ

Υ

141L2AA/AT

Supported Components

HP Z2 Tower Dust Filter and bezel	Υ	Υ	141L3AA/AT
HP PCIe x1 Parallel Port Card	Υ	Υ	N1M40AA
HP Z2 G9 Single Type-C SuperSpeed USB 20Gbps Front Port	Υ	Υ	4M9X8AA/AT
HP Z2 TWR Dual Front Fan Kit	Υ	Υ	4N007AA
HP Optical Bay HDD Mounting Bracket	Υ	Υ	NQ099AA
HP Z2 Tower HDD Cable Kit	N	Υ	6Z9U6AA
HP Anyware Integrated Remote System Controller	Υ	Υ	7K6D9AA
HP Anyware Remote System Controller Main Board Adapter	Υ	Υ	7K6D8AA
HP Anyware Remote System Controller	Υ	Υ	7K6D7AA
HP Anyware Remote System Controller for Universal KVM	N	Υ	7K7N2AA

Racking and Physical Security		Factory Configured	Option Kit Part Number	
	HP Z2 Mini and Z2/Z4/Z6 TWR Depth Adjustable Fixed Rail Rack Kit	Υ	Υ	2A8Y5AA
	HP Keyed Cable Lock	Υ	Υ	T1A62AA
	HP Master Keyed Cable Lock 10mm	Υ	Υ	T1A63AA
	HP Business PC Security Lock V3 Kit	Υ	Υ	3XJ17AA

Software		Factory Configured	Option Kit	Support Notes
	HP Performance Advisor	Υ	N	1
	HP PC Hardware Diagnostics UEFI (Windows OS only)	Υ	N	2
	HP PC Hardware Diagnostics Windows		N	3
	HP Wolf Security	Υ	N	
	HP Notifications	Υ	N	
	HP Desktop Support Utility	Υ	N	
	HP Documentation	Υ	N	
	HP Image Assistant	N	N	
	HP Support Assistant	N	N	
	myHP	Υ	N	
	HP Easy Clean	Υ	N	
	Kingsoft WPS Office	Υ	N	4
	My Office	Υ	N	5
	Adobe Substance 3D Collection Plan	N	Υ	6
	WSL2/Ubuntu Data Science Stack	Υ	N	7

Notes:

- 1. Supports, and preinstalled with Windows 10 only. Also available as a free download from http://www.hp.com/go/performanceadvisor
- 2. Windows OS only
- 3. Not available in Russia
- 4. Only available in China
- 5. Only available in Russia
- 6. Not available in China
- 7. Optional Software



Supported Components

Operating Systems

Windows 11 Pro - HP recommends Windows 11 Pro²

Windows 11 Home - HP recommends Windows 11 Pro²

Windows 10 Pro (available through downgrade rights from Windows 11 Pro) 1,2,3

Linux®-ready⁵

Ubuntu®4,5

- o Intel 12th generation processors will support and preinstall Ubuntu 20.02 and 20.04.
- o Intel 13th generation processors support and preinstall Ubuntu 22.04 LTS

¹ Device comes with Windows 10 and a free Windows 11 upgrade or may be preloaded with Windows 11. Upgrade timing may vary by device. Features and app availability may vary by region. Certain features require specific hardware (see Windows 11 Specifications).

² Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows is automatically updated and enabled. High speed internet and Microsoft account required. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com.

³This system is preinstalled with Windows 10 Pro software and also comes with a license for Windows 11 Pro software and provision for recovery software. You may only use one version of the Windows software at a time. Switching between versions will require you to uninstall one version and install the other version. You must back up all data (files, photos, etc.) before uninstalling and installing operating systems to avoid loss of your data.

⁴ Not all features are available in all editions or versions of Ubuntu. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS to take full advantage of Ubuntu functionality. Ubuntu may be automatically updated. ISP fees may apply and additional requirements may apply over time for updates.

⁵For detailed Linux[®] OS/hardware support information, see:

http://www.hp.com/support/linux_hardware_matrix

NOTE: Your product does not support Windows 8 or Windows 7. In accordance with Microsoft's support policy, HP does not support the Windows® 8 or Windows 7 operating system on products configured with Intel® and AMD® 7th generation and forward processors or provide any Windows® 8 or Windows 7 drivers on http://www.support.hp.com. A full list of HP products and the Windows 10 versions tested is available on the HP support website. https://support.hp.com/us-en/document/c05195282



Supported Components

HP BIOS

Additional HP BIOS Features:

- Power-On password Helps prevent an unauthorized user from powering on the system.
- Administrator password Also known as the BIOS Setup password, this helps prevent unauthorized changes to the system configuration. If the administrator password is not known, the BIOS cannot be updated and changes cannot be made to BIOS settings using BIOS Setup or under the OS.
- S4/S5 Maximum Power Savings setting supports EU Lot6 requirement and allows the computer to power down below 0.5W in S4/S5 (when turned off). When S4/S5 Maximum Power Savings feature is enabled below features are turned off:
 - -Power to expansion connectors / slots
 - -Most Wake events other than power buttons and WOL(Wake on LAN supported by embedded Lan controller under S4/S5 Maximum Power Saving Enabled)
 - -USB charging ports

HP Sure Start Gen7 Start

- BIOS Integrity checking Sure Start protection ensures that only trusted BIOS code is executed and not rootkits, viruses and malware. Verification is done upon boot up, shutdown and while the system is on.
- Sure Start is set by default to automatically repair the BIOS if corrupted or compromised but is policy driven for better manageability. Start is set by default to automatically repair the BIOS if corrupted or compromised but is policy driven for better manageability.
- Protecting beyond BIOS Integrity checking and repair is extended to other data that should be protected such as network configuration parameters, platform specific information (i.e. system IDs), secure boot credentials, and other code the system needs to boot.
- Audit enabled System Audit via Sure Start Event Logs capture data such as incident, repair date and time for troubleshooting and investigating

NOTE: HP Sure Start Gen7 is available on HP Workstation products equipped with Intel® 12th generation processors.

HP Performance Control Modes

HP Z Desktop Workstations offers Performance Control Modes in the F10 BIOS menu. Z2 G9 offers Quiet Mode, Performance Mode and High-Performance Mode. HP recommends using High Performance Mode unless you have concerns about acoustics in an open office environment. Customers can get up to 34% performance improvements using High Performance Mode over Performance Mode*. It is possible to configure High Performance Mode as default from the factory.

How to Set HP Performance Control Modes in HP F10 BIOS Menu

In the F10 BIOS Menu, the setting titled "Performance Control" is adjustable to High Performance Mode, Performance Mode or Quiet Mode. These modes are choice points for performance and acoustic trade-offs based on user needs or recommended balanced conditions in performance and noise optimization.

At startup, push the F10 key while system is booting to get to the BIOS Menu.

Go to --> Advanced -> System Options ->scroll down and choose "Performance Control"

Set the Performance Mode you desire and then go back to Main->Save Changes and Exit -> Yes

The machine will restart in the mode you've chosen.



Supported Components

You can change these modes anytime you prefer to prioritize acoustics (Quiet Mode), want a balance between performance and acoustics (Performance Mode) or prefer to prioritize performance (High Performance Mode).

For more information on performance control modes, please see the white paper called, HP Performance Control Modes for Z Desktop Workstations.

*Compared to Performance Mode. Performance increase based on Z2 Tower G9 with 64GB of memory, 1TB NVMe, Windows 11 22H2 OS, RTX A4000, i9-13900 CPU using SPECworkstation 3.1

SOFTWARE COMPONENTS AND APPLICATIONS WITH WINDOWS

Software

HP Support Assistant 14

HP Image Assistant

HP Desktop Support Utility

HP Documentation

HP Notifications

HP PC Hardware Diagnostics UEFI

HP PC Hardware Diagnostics Windows

HP Performance Advisor1

myHP

HP Easy Clean²⁰

WSL/Ubuntu Data Science Stack

HP Privacy Settings

Touchpoint Customizer for Commercial

Manageability Features

HP Driver Packs²

HP UWP Pack

HP System Software Manager (SSM)

HP Manageability Integration Kit Gen43

HP Smart Support⁵

HP Client Catalog (download)

HP Image Assistant (download)

HP Cloud Recovery

HP Client Management Script Library (download)

HP BIOSphere Gen6 13

Client Security Software

HP Client Security Suite Gen74 including: (including Credential Manager, HP Password Manager6, HP Spare Key)

HP Power On Authentication

Microsoft Defender⁷

Security Management

HP Secure Erase 16

HP Wolf Pro Security Edition (optional) 18

HP Wolf Security for Business²² Includes:

HP Sure Click¹¹

HP Sure Sense¹²

HP Sure Run Gen59

HP Sure Recover Gen4 10

HP Sure Start Gen78



Supported Components

HP Tamper Lock HP Sure Admin ¹⁷ HP Client Security Manager Gen 7⁴

- ¹ HP Performance Advisor Software HP Performance Advisor is ready to help you get the most out of your HP Workstation from day one—and every day after. Learn more or download at: http://hp.com/PerformanceAdvisor
- ² HP Driver Packs not preinstalled, however available for download at http://www.hp.com/go/clientmanagement.
- ³ HP Manageability Integration Kit can be downloaded from http://www8.hp.com/us/en/ads/clientmanagement/overview.html
- ⁴ HP Client Security Manager Gen7 requires Windows and is available on the select HP PCs.
- ⁵ HP Smart Support automatically collects the telemetry necessary upon initial boot of the product to deliver device-level configuration data and health insights and is available preinstalled on select products, thru HP Factory Configuration Services; or it can be downloaded. For more information about how to enable HP Smart Support or for download, please visit http://www.hp.com/smart-support.
- ⁶ HP Password Manager requires Internet Explorer or Chrome or FireFox. Some websites and applications may not be supported. User may need to enable or allow the add-on / extension in the internet browser.
- ⁷ Microsoft Defender Opt in and internet connection required for updates.
- ⁸ HP Sure Start Gen 7 is available on select HP PCs and workstations. See product specifications for availability.
- ⁹ HP Sure Run Gen5 is available on select Windows 11 based HP Pro, Elite and Workstation PCs with select Intel® or AMD processors
- ¹⁰ HP Sure Recover Gen4 is available on select HP PCs and requires Windows 10 and an open network connection. You must back up important files, data, photos, videos, etc. before using HP Sure Recover to avoid loss of data. Network based recovery using Wi-Fi is only available on PCs with Intel Wi-Fi Module
- ¹¹ HP Sure Click requires Windows 10 Pro or higher or Enterprise. See https://bit.ly/2PrLT6A_SureClick for complete details.
- ¹² HP Sure Sense requires Windows 11 Pro or Enterprise and supports Microsoft Internet Explorer, Google Chrome™, and Chromium™. Supported attachments include Microsoft Office (Word, Excel, PowerPoint) and PDF files in read only mode, when Microsoft Office or Adobe Acrobat are installed.
- 13 HP BIOSphere Gen6 features may vary depending on the platform and configurations.
- ¹⁴ HP Support Assistant requires Windows and Internet access.
- ¹⁶ Secure Erase For the methods outlined in the National Institute of Standards and Technology Special Publication 800-88 "Clear" sanitation method. HP Secure Erase does not support platforms with Intel® Optane.
- ¹⁷ HP Sure Admin requires Windows 11, HP BIOS, HP Manageability Integration Kit from
- http://www.hp.com/go/clientmanagement and HP Sure Admin Local Access Authenticator smartphone app from the Android or Apple store.
- ¹⁸ HP Wolf Pro Security Edition is available preloaded on select SKUs and, depending on the HP product purchased, includes a paid 1-year or 3-year license. The HP Wolf Pro Security Edition software is licensed under the license terms of the HP Wolf Security Software End-User license Agreement (EULA) that can be found at: https://support.hp.com/us-
- en/document/ish_3875769-3873014-16 as that EULA is modified by the following: "7. Term. Unless otherwise terminated earlier pursuant to the terms contained in this EULA, the license for the HP Wolf Pro Security Edition (HP Sure Sense Pro and HP Sure Click Pro) is effective upon activation and will continue for either a twelve (12) month or thirty-six (36) month license term ("Initial Term"). At the end of the Initial Term you may either (a) purchase a renewal license for the HP Wolf Pro Security Edition from HP.com, HP Sales or an HP Channel Partner, or (b) continue using the standard versions of HP Sure Click and HP Sure Sense at no additional cost with no future software updates or HP Support.
- ²⁰ HP Easy Clean requires Windows 10 RS3 and higher and will disable the keyboard, touchscreen, and clickpad only. Ports are not disabled. See user guide for cleaning instructions.
- ²² HP Wolf Security for Business requires Windows 10 or higher, includes various HP security features and is available on HP Pro, Elite, RPOS and Workstation products. See product details for included security features



4400MHz

QuickSpecs

System Technical Specifications

System Board

System Board Form

Factor Customized PCB 36.056 x 25.130 mm (14.197 x 9.894 inch)

Processor Socket Single LGA-1700

CPU Bus Speed DMI Gen4

Chipset Intel® PCH W680 Super I/O Controller Nuvoton SIO21

Memory Expansion Slots 4 DDR5 memory slots

Memory Type Supported DDR5, UDIMM (Unbuffered), ECC& non-ECC

Memory Modes Non-Interleaved for single channel. Interleaved when both channels are populated.

Memory Speed Supported 3600MT/s to 4400MT/s DDR5, dependent on memory configuration1

¹Though the memory modules can run up to 4800MHz, the current platform will only be able to support the maximum memory speed of 4400MHz.

The system speed will be determined by a number of key factors:

Description of configuration Module **Max Memory Speed (Actual Memory** Configuration speed is dependent on CPU)

Single DIMM per Configurations that contain only one or two

channel DIMM modules with DIMMs only in the black slots

Two single ranked Configurations with 3 or 4 single ranked DIMMs 4000MHz DIMMs in a channel (8GB and 16GB) installed in a system

Two dual ranked Configurations with 3 or 4 dual ranked DIMMs 3600MHz

DIMMs in a channel (32GB) installed in a system

Memory Protection ECC available on data

Maximum Memory 128GB

Memory Configuration

(Supported)

8GB, 16GB and 32GB non-ECC, 16GB and 32GB ECC unbuffered DIMMs are supported. ECC and non-ECC memory DIMMs cannot be mixed in the same system

PCI Express Connectors (1) PCI Express Gen5 slot x16 mechanical/x16 electrical (full height, full length)

(1) PCI Express Gen3 slot x4 mechanical/x1 electrical (full height, full length, open-ended)

(1) PCI Express Gen3 slot x16 mechanical/ x4 electrical (full height, full length)

(1) PCI Express Gen3 slot x4 mechanical/ x4 electrical (full height, full length, open-ended)

(1) M.2 2280 Storage (PCIe Gen4 x4) (1) M.2 2280 Storage (PCIe Gen4 x4) (1) M.2 2280 Storage (PCIe Gen4 x4)

(1) M.2 2230 WLAN (PCIe Gen3 x1+ Intel CNVi)

NOTE: The PCIe Gen5 x16 slot has validated and passed PCI-SIG electrical compliance test ONLY. HP does not quarantee and support any PCIe Gen5 cards available -in the open market. May or may not see performance reduced when device MRRS (Maximum Read Request Size) is 512Bytes and above. To reach highest Gen5 PCIe performance, Use the top bin DRAM module (e.g. 4400) to minimize the impact.

Supported Interfaces SATA Integrated (4) Serial ATA interfaces (6Gb/s SATA).

RAID 0 and 1 supported. Factory integrated RAID for

Microsoft Windows only.

Intel® UHD Graphics 730 (on Core i5-12400/i3-12300/i3-**Integrated Graphics**

12100) processors); Intel® UHD Graphics 770 (on Core

i5/i7/i9 processors):

System Technical Specifications

Based on Unified Memory Architecture (UMA) - a region of system memory is reserved and dedicated to the graphics display.

Support for Microsoft DirectX 12, OpenGL 4.6 and OpenCL 3.0

on Intel® UHD Graphics 730/770:

Based on Unified Memory Architecture (UMA) - a region of system memory is reserved and dedicated to the graphics

display.

2 DP 1.4 graphics ports integrated in motherboard; Supports

up to three simultaneous displays across

DisplayPort*/HDMI*/DVI outputs.

Max. resolution supported on onboard DP 1.4/HBR2 ports:

4096x2304 @ 60Hz, 24bpp

Max. resolution supported on FlexIO DP 1.4/HBR3 port:

5120x3200 @60Hz, 24bpp

Network Controller Integrated Ethernet PHY Connection I219LM. Management

capabilities: WOL, PXE 2.1 and AMT 16

Serial 1 internal header (requires optional Serial Port and PS/2

Combo Kit with PCIe bracket)

2nd Serial 1 internal header(requires optional Serial Port Adapter Kit)

USB Connector(s)Front
2 Type-A SuperSpeed USB 10Gbps signaling rate port (charge

supports up to 5V/2.1A);

2 Type-A SuperSpeed USB 10Gbps signaling rate port; 1 Type-C[®] SuperSpeed USB 20Gbps signaling rate port

(optional, charge supports up to 5V/3A)

Rear 3 High-speed USB 480Mbps signaling rate port; 1 Type-A

SuperSpeed USB 5Gbps signaling rate port; 2 Type-A

SuperSpeed USB 10Gbps signaling rate port;

Flex I/O option:

1 SuperSpeed USB Type-C[®] 10Gbps signaling rate (Power Delivery 15W, Alt Mode DisplayPort); 1 Dual SuperSpeed USB

Type-A 5Gbps signaling rate

Internal 1 High-speed USB 480Mbps signaling rate header for SD Card

Reader

HD Integrated Audio Realtek ALC3205

Flash ROM Yes
CPU Fan Header Yes
Memory Fan Header None

Chassis Fan Header 1 Rear System Chassis Fan Header, 1 Graphic chassis Fan Header.

Front PCI Fan Header None

Front Control

Panel/Speaker Header Yes

CMOS Battery Holder -

Lithium Yes

Integrated Trusted Integrated TPM 2.0 (Infineon SLB9672)

Platform Module Convertible to FIPS 140-2 Certified mode through firmware v15.21

Power Supply Headers Yes
Power Switch, Power LED
& Hard Drive LED Header Yes
Clear Password Jumper None



System Technical Specifications

Keyboard/Mouse USB or PS/2 (option)

Power Supply 700W EPA92, 500W EPA90, 450W EPA90 and 350W EPA92

¹Maximum memory capacities assume 64-bit operating systems, such as Genuine Windows® 10 Professional 64 bit, Red Hat Linux 64-bit. 32-bit Windows Operating Systems support up to 4 GB.

PROCESSORS

Name	Ghz P- Core Base Frequenc	Ghz E- Core Base Frequenc	Core Max	Up to x GHz E-Core Max Turbo Frequency	L3 Cache (MB)	P- Core S	E- Core s	Total Cores	Processo r Threads	Memory Speed (MT/s) (DDR5) ⁴	ECC Memory Supporte d ⁵	Integrated Graphics	Featuring Intel® vPro® Technolog v³	TDP (W)	Max Turbo Freque ncy (GHz) ²
Intel 13 th Gene			1		1			1		ı		ı			, (,
Intel® Core™ i9-13900K	3	2.20	5.4	4.3	36	8	16	24	32	5600	Y	Intel® UHD Graphics 770	Y	125	5.8
Intel® Core™ i9-13900	2	1.50	5.2	4.2	36	8	16	24	32	5600	Y	Intel® UHD Graphics 770	Y	65	5.6
Intel® Core™ i7-13700K	3.4	2.50	5.3	4.2	30	8	8	16	24	5600	Y	Intel® UHD Graphics 770	Y	125	5.8
Intel® Core™ i7-13700	2.1	1.50	5.1	4.10	30	8	8	16	24	5600	Y	Intel® UHD Graphics 770	Y	65	5.2
Intel® Core™ i5-13600K	3.5	2.60	5.1	3.9	24	6	8	14	20	5600	Y	Intel® UHD Graphics 770	Y	65	5.1
Intel® Core™ i5-13600	2.7	2.00	5.0	3.7	24	6	8	14	20	4800	Υ	Intel® UHD Graphics 770	Y	65	5.0
Intel® Core™ i5-13500	2.5	1.80	4.8	3.5	24	6	8	14	20	4800	Υ	Intel® UHD Graphics 770	Y	65	4.8
Intel® Core™ i5-13400	2.5	1.80	4.6	3.3	20	6	4	10	16	4800	N	Intel® UHD Graphics 730	N/A	65	4.6
Intel 12 th Gene	eration Pro	ocessors										'			
Intel® Core™ i9-12900K	3.2	2.4	5.1	3.9	30	8	8	16	24	4800	Υ	Intel® UHD Graphics 770	Y	125	5.2
Intel® Core™ i9-12900	5	1.8	5.0	3.8	30	8	8	16	24	4800	Y	Intel® UHD Graphics 770	Y	65	5.1
Intel® Core™ i7-12700K	3.6	2.7	4.9	3.8	25	8	4	12	20	4800	Y	Intel® UHD Graphics 770	Y	125	5.0
Intel® Core™ i7-12700	2.1	1.6	4.8	3.6	25	8	4	12	20	4800	Υ	Intel® UHD Graphics 770	Y	65	4.9
Intel® Core™ i5-12600K	3.7	2.8	4.9	3.6	20	6	4	10	16	4800	Y	Intel® UHD Graphics 770	Y	125	4.9
Intel® Core™ i5-12600	3.3	N/A	4.8	N/A	18	6	0	6	12	4800	Y	Intel® UHD Graphics 770	Y	65	4.8
Intel® Core™ i5-12500	3	N/A	4.6	N/A	18	6	0	6	12	4800	Y	Intel® UHD Graphics 770	Y	65	4.6
Intel® Core™ i5- 12400	2.5	N/A	4.4	N/A	18	6	0	6	12	4800	N	Intel® UHD Graphics 730	N/A	65	4.4
Intel® Core™ i3-12300	3.5	N/A	4.4	N/A	12	4	0	4	8	4800	N	Intel® UHD Graphics 730	N/A	60	4.4



²M.2 storage supports compatible devices up to 80mm

Intel® Core™ i3-12100	3.3	N/A	4.3	N/A	12	4	0	4	8	4800	N	Intel® UHD Graphics 730	N/A	60	4.3
	applicati dependi and/or n	ions will ing on applanting is	necessari plication not a me	ly benefit workload asuremer	from u and yo nt of hi	ise o ur ha gher	f this Irdwa perfo	technore are and ormand	ology. P I softwa ce.	erformar re config	nce and juration	ll customers or clock frequency s. Intel's numbe M in your syste	y will var ering, bra	y	3
				nance var hnology/t			_				nd overa	all system confi	iguratior	ı. See	
	wired LA	N and/or	Wi-Fi 6E		d TPM	2.0. 9	ome	functi	onality r	equires a	addition	vPro enabled c aal 3rd party so			
		thin 2DIM										will run at 4000) in 2DPC withir			



System Configuratio	ns						
Example Configuration	Processor Info	Core i5-12500	0,6C 3.0G 65W				
#1	Memory Info	2 x 8G DDR5 4	1800 UDIMM NE	ECC			
	Graphics Info	NVIDIA T400	4GB				
	Disks/Optical/Floppy	512GB SSD Z	Turbo				
	PSU	350W					
	Other	NA					
Energy Consumption		115	VAC	230	VAC	100	VAC
(Watts)		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled
	Windows long Idle (S0)	17.	866	17.912		17.	804
	Windows short Idle (S0)	18.	926	19.	024	18.	883
	Windows Busy Typ (S0)	160	.167	155.	.973	161	.10
	Windows Busy Max (S0)	192	.557	187	.067	193	.063
	Sleep (S3)	1.367	1.259	1.401	1.367	1.259	1.401
	Off (S5)	0.555	0.552	0.561	0.555	0.552	0.561
	Zero Power Mode (EuP)	0.1	71	0.1	73	0.1	68
Heat Dissipation		115 VAC		230	VAC	100	VAC
(Btu/hr)		LAN	LAN	LAN	LAN	LAN	LAN
		Enabled	Disabled	Enabled	Disabled	Enabled	Disabled
	Windows Idle (S0)		959	61.		60.	
	Windows short Idle (S0)	64.576		64		I	429
	Windows Busy Typ (S0)	546.489		532		1	.707
	Windows Busy Max (S0)	657.003		638	I	658	-
	Sleep (S3)	4.664	4.296	4.78	4.664	4.296	4.78
	Off (S5)	1.894	1.883	1.914	1.894	1.883 1.914	
	Zero Power Mode (EuP)	0.583 0.59 0.573					
Example Configuration #2	Processor Info	Core i7-12700,12C 2.1G 65W					
π 2	Memory Info		4800 UDIMM N	NECC			
	Graphics Info	NVIDIA T1000					
	Disks/Optical/Floppy	512GB SSD Z	Turbo				
	PSU	450W					
	Other	NA		T		T	
	I .	115	VAC	230 VAC		100 VAC	
Energy Consumption							
Energy Consumption (Watts)		LAN	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled
	Windows long Idle (S0)	LAN Enabled	LAN Disabled	LAN Enabled 20.	Disabled	Enabled	LAN Disabled 087
	Windows long Idle (S0) Windows short Idle (S0)	LAN Enabled 20.	Disabled	Enabled	Disabled 335	Enabled 20.	Disabled
	Windows short Idle (S0)	LAN Enabled 20.	Disabled 169 222	Enabled 20.	Disabled 335 547	Enabled 20.	Disabled 087 195
	Windows short Idle (S0) Windows Busy Typ (S0)	LAN Enabled 20.	Disabled 169 222 0.48	Enabled 20 21 117	Disabled 335 547 953	Enabled 20.1 21. 120.	Disabled 087 195 .406
	Windows short Idle (S0) Windows Busy Typ (S0) Windows Busy Max (S0)	LAN Enabled 20. 21. 119	Disabled 169 222 0.48 7.13	Enabled 20 21 117	Disabled 335 547 953	Enabled 20.0 21.0 120.0 157.0	Disabled 087 195 406 833
	Windows short Idle (S0) Windows Busy Typ (S0)	LAN Enabled 20.	Disabled 169 222 0.48	Enabled 20 21 117	Disabled 335 547 953	Enabled 20.1 21. 120.	Disabled 087 195 .406



Heat Dissipation		115	VAC	230	VAC	100	VAC		
(Btu/hr)		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled		
	Windows Idle (S0)	68.	817	69.	383	68.537			
	Windows short Idle (S0)	72.	409	73.	518	72.	317		
	Windows Busy Typ (S0)	407	.666	402	.457	410	.824		
	Windows Busy Max (S0)	536	.128	528	.962	538	.527		
	Sleep (S3)	5.374	4.985	5.398	5.374	4.985	5.398		
	Off (S5)	3.221	3.211	3.248	3.221	3.211	3.248		
	Zero Power Mode (EuP)	0.6	0.696 0.706 0.689						
Example Configuration	Processor Info	Core i9-12900,16C 2.4G 65W							
#3	Memory Info	2 x 16G DDR5	4800 UDIMM E	:CC					
	Graphics Info	NVIDIA RTX A	2000						
	Disks/Optical/Floppy	512GB SSD Z	Turbo						
	PSU	450W							
	Other	NA							
Energy Consumption		115	VAC	230 VAC		100 VAC			
(Watts)		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled		
	Windows long Idle (S0)	22.	555	23.	324	22.	484		
	Windows short Idle (S0)	23.	414	24.	656	23.	397		
	Windows Busy Typ (S0)	159	.883	156	.853	161	.463		
	Windows Busy Max (S0)	189	9.99	185	5.89	190	.127		
	Sleep (S3)	1.585	1.492	1.694	1.585	1.492	1.694		
	Off (S5)	0.952	0.95	1.083	0.952	0.95	1.083		
	Zero Power Mode (EuP)	0.	21	0.2	217	0.198			

Heat Dissipation		115	VAC	230	VAC	100	VAC
(Btu/hr)		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled
	Windows Idle (S0)	76.958		79.581		76.715	
	Windows short Idle (S0)	79.	79.889		84.126		79.831
	Windows Busy Typ (S0)	545.522		535.184		550.913	
	Windows Busy Max (S0)	648	.246	634.257		648.712	
	Sleep (S3)	5.408	5.091	5.78	5.408	5.091	5.78
	Off (S5)	3.248	3.241	3.695	3.248	3.241	3.695
	Zero Power Mode (EuP)	0.7	17	0.74		0.676	

Example Configuration	Processor Info	Core i7-12700K,12C 3.6G 125W				
#4	Memory Info	4 x 16G DDR5 4800 UDIMM NECC				
	Graphics Info	NVIDIA RTX A4000				
	Disks/Optical/Floppy	1T SSD Z Turbo				
	PSU	700W				
	Other	NA				



Energy Consumption		115	VAC	230	VAC	100 VAC			
(Watts)		LAN Enabled	LAN Enabled LAN Disabled		LAN Disabled	LAN Enabled	LAN Disabled		
	Windows long Idle (S0)	22.551		22.964		22.486			
	Windows short Idle (S0)	23.911		24.168		23.749			
	Windows Busy Typ (S0)	272.74		267.963		274.65			
	Windows Busy Max (S0)	322	.833	316	.03	323.	323.367		
	Sleep (S3)	1.994	1.892	1.997	1.994	1.892	1.997		
	Off (S5)	0.653	0.641	0.666	0.653	0.641	0.666		
	Zero Power Mode (EuP)	0.2	215	0.217		0.212			

Heat Dissipation		115	115 VAC		VAC	100	VAC	
(Btu/hr)		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	
	Windows Idle (S0)	76.	76.944		78.353		76.722	
	Windows short Idle (S0)	81.584		82.461		81.032		
	Windows Busy Typ (S0)	930.589		914.291		937.106		
	Windows Busy Max (S0)	1101	.507	1078	.294	1103.327		
1	Sleep (S3)	6.804	6.456	6.814	6.804	6.456	6.814	
	Off (S5)	2.228	2.187	2.272	2.228	2.187	2.272	
	Zero Power Mode (EuP)	0.734		0.74		0.723		

Example Configuration	Processor Info	Core i9-12900K,16C 3.2G 125W			
#5	Memory Info	4 x 32G DDR5 4800 UDIMM ECC			
	Graphics Info	NVIDIA RTX A5000			
	Disks/Optical/Floppy	1T SSD Z Turbo			
	PSU	700W			
	Other	NA			

Energy Consumption		115	VAC	230 VAC		100 VAC		
(Watts)		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	
	Windows long Idle (S0)	24.	24.038		24.681		23.994	
	Windows short Idle (S0)	25.	25.764		25.958		25.621	
	Windows Busy Typ (S0)	465.05		459.71		468.377		
	Windows Busy Max (S0)	467	.623	438.733		474.68		
	Sleep (S3)	2.261	2.148	2.273	2.261	2.148	2.273	
	Off (S5)	0.772	0.659	0.777	0.772	0.659	0.777	
	Zero Power Mode (EuP)	0.3	0.318		0.319		0.315	

Heat Dissipation		115 VAC		230 VAC		100 VAC	
(Btu/hr)		LAN Enabled LAN Disabled		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled
	Windows Idle (S0)	82.018		84.212		81.868	
	Windows short Idle (S0)	87.907		88.569		87.419	
	Windows Busy Typ (S0)	158	6.75	1568.531		1598.101	
	Windows Busy Max (S0) 1595.531		1496.958		1619	1619.608	
	Sleep (S3)	7.715	7.329	7.755	7.715	7.329	7.755

System Technical Specifications

Off (S5)	2.634	2.249	2.651	2.634	2.249	2.651
Zero Power Mode (EuP)	1.0	85	1.0	88		75

NOTE: The Power Supply Efficiency report may be found at the following links:

https://www.plugloadsolutions.com/80PlusPowerSuppliesDetail.aspx?id=0&type=2



System Technical Specifications

Operating Voltage Range 90-269 VAC **Rated Voltage Range** 100-240 VAC **Rated Line Frequency** 50-60 Hz **Operating Line Frequency** 47-63 Hz

Range

Rated Input Current 8.2A @ 100-240V

Heat Dissipation Typical: 1598.101 btu/hr (402.984 kcal/hr)

Yes

Yes

Maximum: 1619.608 btu/hr (408.407 kcal/hr)

Yes, with Wake-on-LAN disabled: <1W in S4/S5 - Power Off

ENERGY STAR® certified

(Config Dependent)

CECP Compliant @ 220V Yes

FEMP Standby Power

Compliant

Built-in Self Test (BIST)

LED

Surge Tolerant Full Yes **Ranging Power Supply** (withstands power surges

up to 2000V)

Hood Lock Header Yes ErP Lot 6- Tier 1 Yes Compliance @ 230V (<1W

in S5 - Power Off)

ErP Lot 6- Tier 2 Yes

Compliance @ 230V (<0.5W in S5 - Power Off)

Declared Noise Emissions	(Entry-level, Mid-level, a	nd High-end configurations; tested on flo	oor)
System Configuration	Processor Info	Intel® CPU Core i5-12400 6C LGA 2.50	G 18 MB 65W (Intel - Alder Lake-S)
(Entry level)	Memory Info	32GB 4800 SK hynix memory	
	Graphics Info	Intel® UHD	
	Disks/Optical	1*2TB Samsung M.2 SSD	
	Power Supply	Chicony 700W EPA92	
Declared Noise Emissions		Sound Power (LWAd, bels)	Deskside Sound Pressure (LpAm, decibels)
	Idle	3.36	14.9
	Hard drive Operating (Drive Random Seek)	3.78	20.3
	Hard drive Operating (Active mode)	3.45	17.7
System Configuration (Mid-level)	Processor Info	Intel® CPU Core i9-12900 16C LGA 2.4 S)	OG 30 MB 65W ECC (Intel - Alder Lake-
	Memory Info	4* 32GB 4800 SK hynix memory	
	Graphics Info	NVIDIA® RTX A5000	
	Disks/Optical	3*2TB Samsung M.2 SSD; 2*WD 2TB 7	200RPM SATA HDD
	Power Supply	Chicony 700W EPA92	



System Technical Specifications

Declared Noise Emissions		Sound Power (LWAd, bels)	Deskside Sound Pressure (LpAm, decibels)
	Idle	3.59	18.5
	Hard drive Operating (Drive Random Seek)	3.82	20.1
	Hard drive Operating (Active mode)	3.97	23.6
System Configuration	Processor Info	Intel® Core i9-12900K 16C 3.20G LGA 30 MB 125W ECC (Intel - Alder Lake-S)	
(High-end)	Memory Info	4* 32GB 4800 SK hynix memory	
	Graphics Info	NVIDIA® RTX A5000	
	Disks/Optical	3*2TB Samsung M.2 SSD; 2*WD 2TB 7200RPM SATA HDD	
	Power Supply	Chicony 700W EPA92	
Declared Noise Emissions		Sound Power (LWAd, bels)	Deskside Sound Pressure (LpAm, decibels)
	Idle	3.58	18.2
	Hard drive Operating (Drive Random Seek)	3.78	20
	Hard drive Operating (Active mode)	4.05	20.9
		-	

Environmental
Requirements

Temperature Operating: 5° to 35° C (40° to 95° F)

Non-operating: -40° to 60° C (-40° to 140° F)

Maximum rate of change: 10°C/hr

Humidity Operating: 10% to 85% RH, non-condensing, 35° C maximum wet bulb

Non-operating: 10% to 90% RH, non-condensing, 35° C maximum wet bulb

Maximum Altitude Operating (with Rotational Hard Drives): 3,048 m (10,000 feet)

Operating (with only Solid-State Drives): 5,000 m (16,404 feet)

Non-operating: 12,192 m (40,000 feet)

Maximum operating temperature is reduced as altitude increases. See

Cooling for details.

Dynamic Shock

Operating: ½-sine: 40g, 2-3ms (~62 cm/sec) Non-operating: ½-sine: 160 cm/s, 2-3ms (~105g)

square: 422 cm/s, 20q

Vibration

Operating random: 0.5g (rms), 5-300 Hz, up to 0.0025g²/Hz Non-operating random: 2.0g (rms), 5-500 Hz, up to 0.0150 g²/Hz

Cooling Above 1524 m (5,000 feet) altitude, the maximum operating temperature

is reduced by 1° C (1.8° F) for every 305 m (1,000 feet) increase in elevation,

up to 3048 m (10,000 feet)

NOTE: System enduring or operating beyond the environmental requirement

range is not recommended and may compromise system reliability

permanently.



System Technical Specifications

Physical Security and Serviceability

Access Panel Tool-less

Includes support information

Optical Drive Tool-less, except for Screw-In carrier

Hard Drives Tool-less, except for 2.5" bay

Expansion Cards Tool-less

Processor Socket Tool-less, except for the processor heatsink **Blue User Touch Points** Yes, on tool-less internal chassis mechanisms

Color-coordinated Cables Yes

and Connectors

MemoryTool-lessSystem BoardScrew-In

Padlock Support Yes (optional): Locks side cover and secures chassis from theft

0.22-in diameter padlock loop at rear of system

Cable Lock Support
Yes, Kensington Cable Lock (optional): Locks side cover and secures chassis from theft

3 mm x 7 mm slot at rear of system

Universal Chassis Clamp

Lock Support

Yes (optional): Locks side cover and locks cables to chassis. Secures chassis from theft and allows

multiple units to be chained together when used with optional cable

Threaded feature at rear of system

Solenoid Lock and Hood

Sensor

Yes (optional)

The Solenoid Hood Lock eliminates the need for a physical key by making the chassis lockable through software and a password. You can also lock and unlock the chassis remotely over the network. The

Sensor Kit detects when the access panel has been removed.

Rear Port Control Cover No

CPUs and Heatsinks A T-15 Torx or flat blade screwdriver is needed to remove the CPU heatsink before the CPU can be

removed. CPU removal is tool-less

Internal Speaker Yes

Power Supply Fans 70mm x 70mm x 25mm 4-wire PWM (non-serviceable)

Access Panel Key Lock No

Integrated Chassis

Handles

Rear Recessed Handle

Power Supply Requires T15 Torx or flat blade screwdriver

PCI Card Retention Yes, rear (all), middle (optional), front (full-length cards with extender)

Service, Support, and Warranty

On-site Warranty and Service¹: Three-years, limited warranty and service offering delivers on-site, next business-day² service for parts and labor and includes free telephone support³ 8am - 5pm. Global coverage² ensures that any product purchased in one country and transferred to another, non-restricted country will remain fully covered under the original warranty and service offering. 24/7 operation will not void the HP warranty. Storage devices are not covered under warranty for 24/7 operation except for Enterprise class HDDs.

NOTE 1: Terms and conditions may vary by country. Certain restrictions and exclusions apply.

NOTE 2: On-site service may be provided pursuant to a service contract between HP and an authorized HP third-party provider, and is not available in certain countries. Global service response times are based on commercially reasonable best effort and may vary by country.

NOTE 3: Technical telephone support applies only to HP-configured, HP and HP-qualified, third-party hardware and software. Toll-free calling and 24x7 support service may not be available in some countries.

HP Care Pack Services extend service contracts beyond the standard warranties. Service starts from date of hardware purchase. To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at:



System Technical Specifications

http://www.hp.com/go/lookuptool. Service levels and response times for HP Care Packs may vary depending on your geographic location.

Certification and Compliance

Environmental Sustainability questions concerning:

- Ecolabels (EPEAT, TCO, etc.)
- ENERGY STAR, California Energy Commission (CEC)
- Compliance with Environmental legislation (EU ErP, China CECP, EU RoHS and other countries)
- Supply Chain Social Environmental Responsibility (SER) (conflict minerals; human rights, etc.)
- Product specific environmental features (material content, packaging content, recycled content, etc.)
- China Energy Label (CEL)

Please contact sustainability@hp.com

For country specific Regulatory Compliance approval documents or Regulatory and Safety questions concerning:

- Declarations of Conformity (for self-service, go to https://www.hp.com/uken/certifications/technical/regulations-certificates.html?jumpid=ex_r135_uk/en/any/corp/hpukmu chev/certificates)
- **GS** Certificates
- Product Safety Certificates (UL. CB. BIS. etc.)
- EMC Certificates, Declarations of Conformity, or Certificates of Conformity (CE, FCC, ICES, etc.)
- **CCC Certificates**
- **Ergonomics**

Please contact techreqshelp@hp.com

BIOS

BIOS 64-bit Services

PCI 3.0 Support

BIOS supports 64-bit Operating systems only.

Full BIOS support for PCI Express through industry standard interfaces.

ATAPI BBS

ATAPI Removable Media Device BIOS Specification Version 1.0.

WMI Support

BIOS Boot Specification v1.01.(Not support)

WMI is Microsoft's implementation of Web-Based Enterprise Management (WBEM) for Windows. WMI is fully compliant with the Distributed Management Task Force (DMTF) Common Information Model (CIM)

and WBEM specifications.

BIOS Boot Spec 1.01+

Provides more control over how and from what devices the workstation will boot. (Not Support)

BIOS Power On ROM Based Computer Users can define a specific date and time for the system to power on. Review and customize system configuration settings controlled by the BIOS.

Setup Utility (F10)

System/Emergency ROM Flash Recovery with

Video

Recovers system BIOS in corrupted Flash ROM.

Replicated Setup

Saves BIOS settings to USB flash device in human readable file (HpSetup.txt).

BiosConfigurationUtility.exe utility can then replicate these settings on machines being deployed

without entering Computer Configuration Utility (F10 Setup).

SMBIOS Boot Control System Management BIOS 3.4, for system management information. Disables the ability to boot from removable media on supported devices.

Memory Change Alert Thermal Alert

Alerts management console if memory is removed or changed. Monitors the temperature state within the chassis. Three modes:

• NORMAL - normal temperature ranges.

ALERTED - excessive temperatures are detected. Raises a flag so action can be taken to avoid

System Technical Specifications

shutdown or provide for a smoother system shutdown.

• SHUTDOWN - excessive temperatures are encountered. Automatically shuts down the computer

without warning before hardware component damage occurs.

Remote ROM Flash Provides secure, fail-safe ROM image management from a central network console.

ACPI (Advanced Allows the system to enter and resume from low power modes (sleep states).

Configuration and Power Enables an operating system to control system power consumption based on the dynamic workload. Management Interface) Makes it possible to place individual cards and peripherals in a low-power or powered-off state without

affecting other elements of the system.

Supports ACPI 6.0 for full compatibility with 64-bit operating systems.

A user-defined string stored in non-volatile memory that is displayed in the BIOS splash screen. **Ownership Tag**

Remote Wakeup/Remote System administrators can power on, restart, and power off a client computer from a remote location.

Shutdown

Instantly Available PC Allows for very low power consumption with guick resume time.

(Suspend to RAM - ACPI

sleep state S3)

Remote System Installation via F12 (PXE

2.1) (Remote Boot from Server)

Allows a new or existing system to boot over the network and download software, including the

operating system.

ROM revision levels

Reports the system BIOS revision level in Computer Configuration Utility (F10 Setup). Version is available through an industry standard interface (SMBIOS and WMI) so that management SW

applications can use and report this information.

System board revision

level

Allows management SW to read revision level of the system board. Revision level is digitally encoded into the HW and cannot be modified. Assesses system health at boot time with selectable levels of testing.

Start-up Diagnostics (Power-on Self-Test)

Auto Setup when new hardware installed

System automatically detects addition of new hardware.

Keyboard-less Operation The system can be booted without a keyboard.

Localized ROM Setup

Common BIOS image supports System Configuration Utility (F10 Setup) menus in 15 languages with

local keyboard mappings.

The user or MIS to set a unique tag string in non-volatile memory. **Asset Tag**

Per-slot Control Allows I/O slot parameters (option ROM enable/disable, bus latency) to be configured individually. Adaptive Cooling Control parameters are set according to detected hardware configuration for optimal acoustics. **Pre-boot Diagnostics** (Pre-video) critical errors are reported via beeps and blinks on the power LED.

UEFI Specification

Revision 2.7

ACPI Advanced Configuration and Power Management Interface. Version 6.0 AT Attachment 6 with Packet Interface (ATA/ATAPI-6), Revision 3b ATA (IDE) CD Boot "El Torito" Bootable CD-ROM Format Specification Version 1.0

EDD Enhanced Disk Drive Specification Version 1.1

BIOS Enhanced Disk Drive Specification Version 3.0(Not support)

Enhanced Host Controller Interface for Universal Serial Bus, Revision 1.0 **EHCI**

PCI PCI Local Bus Specification, Revision 2.3

> PCI Power Management Specification, Revision 1.1 PCI Firmware Specification, Revision 3.0, Draft .7 PCI Express Base Specification, Revision 2.0

PCI Express Base Specification, Revision 3.0 PCI Express Base Specification, Revision 4.0

PCI Express Base Specification, Revision 5.0 Ready

POST Memory Manager Specification, Version 1.01 **PMM**

PCI Express

System Technical Specifications

SATA Specification, Revision 1.0a

Serial ATA 3 Gb/s: Serial ATA Specification, Revision 2.5 Serial ATA 6 Gb/s: Serial ATA Specification. Revision 3.0

SPD JEDEC JESD300-5

TPM Trusted Computing Group TPM Specification Version 2.0 (Infineon SLB 9670).

Common Criteria EAL4+ certified.

FIPS 140-2 Certification TCG TPM Certified products list:

http://www.trustedcomputinggroup.org/certification/tpm-certified-products/

UHCI Universal Host Controller Interface Design Guide, Revision 1.1

USB Universal Serial Bus Revision 1.1 Specification

Universal Serial Bus Revision 2.0 Specification Universal Serial Bus Revision 3.1 Specification Universal Serial Bus Revision 3.2 Specification

SMBIOS System Management BIOS Reference Specification, Version 3.4

External BIOS simulator found at: http://csrsml.itcs.hp.com/

Social and Environmental Responsibility

Eco-Label Certifications & Declarations This product is low halogen except for HP Z Turbo Quad Pro PCIe TLC SSD, CRU QX 428 & QX448 removable storage frames, ConnectX-6 DX Amphenol 10 & 25 Gb Transceivers, power cords, cables, and peripherals. Service parts obtained after purchase may not be Low Halogen.

This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks:

- IT ECO declaration
- US ENERGY STAR®
- US Federal Energy Management Program (FEMP)
- EPEAT[®] Gold registered in the United States. See http://www.epeat.net for registration status in your country.
- TCO Certified
- China Energy Conservation Program (CECP)
- China State Environmental Protection Administration (SEPA)
- Taiwan Green Mark
- Korea Eco-label
- Japan PC Green label*

Sustainable Impact Specifications

- Product Carbon Footprint (hp.com)
- Ocean-bound plastic in System FAN, CPU FAN and Speaker
- 50% post-consumer recycled plastic
- Low halogen
- Outside Box and corrugated cushions are 100% sustainably sourced and recyclable
- Molded Paper Pulp Cushion inside box is 100% sustainably sourced and recyclable

System Configuration

The configuration used for the Energy Consumption and Declared Noise Emissions data for the Notebook model is based on a "Typically Configured Notebook".

Energy Consumption (in accordance with US ENERGY STAR® test

method) 115VAC, 60Hz 230VAC, 50Hz 100VAC, 50Hz

System Technical Specifications

Normal Operation (Sort idle)	34.16 W	34.01 W	34.39 W
Normal Operation (Long idle)	32.77 W	32.74 W	33.15 W
Sleep	2.57 W	2.54 W	2.57 W
Off	0.67 W	0.68 W	0.67 W

NOTE:

Energy efficiency data listed is for an ENERGY STAR® compliant product if offered within the model family. HP computers marked with the ENERGY STAR® Logo are compliant with the applicable U.S. Environmental Protection Agency (EPA) ENERGY STAR® specifications for computers. If a model family does not offer ENERGY STAR® compliant configurations, then energy efficiency data listed is for a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows® operating system.

Heat Dissipation*	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz
Normal Operation (Short idle)	116.8 BTU/hr	116.3 BTU/hr	117.6 BTU/hr
Normal Operation (Long idle)	112.1 BTU/hr	112 BTU/hr	113.4 BTU/hr
Sleep	8.8 BTU/hr	8.7 BTU/hr	8.8 BTU/hr
Off	2.3 BTU/hr	2.3 BTU/hr	2.3 BTU/hr

*NOTE: Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour.

Declared Noise
Emissions
(in accordance with
ISO 7779 and ISO 9290

(in accordance with ISO 7779 and ISO 9296)	Sound Power (L _{WAd} , bels)	Sound Pressure (L _{pAm} , decibels)
Typically Configured – Idle	3.36	14.9
Fixed Disk – Random writes	3.78	20.3
Optical Drive – Sequential reads	5.00	33.4

Longevity and Upgrading

This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the

Spare parts are available throughout the warranty period and or for up to "5" years after the end of production.

Additional Information

- This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive -2011/65/EC.
- This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive - 2002/96/EC.
- This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986).
- This product is in compliance with the IEEE 1680 (EPEAT) standard at the Gold level, see www.epeat.net
- Plastics parts weighing over 25 grams used in the product are marked per ISO11469 and IS01043.
- This product is 94.8% recycle-able when properly disposed of at end of life.



System Technical Specifications

Packaging Materials External: PAPER/Corrugated 1214 g

PAPER/Molded Pulp 890 g

Internal: PLASTIC/Polyethylene low density - 40 g

LDPE

The plastic packaging material contains at least 0.0% recycled content.

The corrugated paper packaging materials contains at least 62.5% recycled content.

RoHS Compliance

HP Inc. complies fully with materials regulations. We were among the first companies to extend the restrictions in the European Union (EU) Restriction of Hazardous Substances (RoHS) Directive to our products worldwide through the HP GSE. HP has contributed to the development of related legislation in Europe, as well as China, India, and Vietnam.

We believe the RoHS directive and similar laws play an important role in promoting industry-wide elimination of substances of concern. We have supported the inclusion of additional substances—including PVC, BFRs, and certain phthalates—in future RoHS legislation that pertains to electrical and electronics products.

We met our voluntary objective to achieve worldwide compliance with the new EU RoHS requirements for virtually all relevant products by July 2013, and we will continue to extend the scope of the commitment to include further restricted substances as regulations continue to evolve.

To obtain a copy of the HP RoHS Compliance Statement, see HP RoHS position statement.

Material Usage

This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at

http://www.hp.com/hpinfo/globalcitizenship/environment/supplychain/gen_specifications.html):

- Asbestos
- Certain Azo Colorants
- Certain Brominated Flame Retardants may not be used as flame retardants in plastics
- Cadmium
- Chlorinated Hydrocarbons
- Chlorinated Paraffins
- Bis(2-Ethylhexyl) phthalate (DEHP)
- Benzyl butyl phthalate (BBP)
- Dibutyl phthalate (DBP)
- Diisobutyl phthalate (DIBP)
- Formaldehyde
- Halogenated Diphenyl Methanes
- Lead carbonates and sulfates
- Lead and Lead compounds
- Mercuric Oxide Batteries
- Nickel finishes must not be used on the external surface designed to be frequently handled or carried by the user.
- Ozone Depleting Substances
- Polybrominated Biphenyls (PBBs)
- Polybrominated Biphenyl Ethers (PBBEs)
- Polybrominated Biphenyl Oxides (PBBOs)
- Polychlorinated Biphenyl (PCB)
- Polychlorinated Terphenyls (PCT)
- Polyvinyl Chloride (PVC) except for wires and cables, and certain retail packaging has been voluntarily removed from most applications.
- Radioactive Substances



System Technical Specifications

• Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)

Packaging Usage

HP follows these guidelines to decrease the environmental impact of product packaging:

- Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials.
- Eliminate the use of ozone-depleting substances (ODS) in packaging materials.
- Design packaging materials for ease of disassembly.
- Maximize the use of post-consumer recycled content materials in packaging materials.
- Use readily recyclable packaging materials such as paper and corrugated materials.
- Reduce size and weight of packages to improve transportation fuel efficiency.
- Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.

End-of-life Management and Recycling

HP offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.

The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.

HP, Inc. Corporate Environmental Information

For more information about HP's commitment to the environment:

Global Citizenship Report

http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html

Eco-label certifications

http://www8.hp.com/us/en/hp-information/environment/ecolabels.html

ISO 14001 certificates:

http://h20195.www2.hp.com/V2/GetDocument.aspx?docname=c04755842 and

http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf

footnotes

- Percentage of ocean-bound plastic contained in each component varies by product
- Recycled plastic content percentage is based on the definition set in the IEEE 1680.1-2018 standard.
- External power supplies, WWAN modules, power cords, cables and peripherals excluded.
- 100% outer box packaging and corrugated cushions made from sustainably sourced certified and recycled fibers.
- Fiber cushions made from 100% recycled wood fiber and organic materials.

Technical Specifications - Hard Drives

SATA Hard Drives for	r HP
Workstations	

500GB SATA 7200 rpm 6Gb/s 3.5" HDD Capacity 500GB
Protocol SATA
Form Factor 3.5"
Controller AHCI

Height 1 in; 2.54 cm

Width Media Diameter 3.5 in; 8.9 cm

Up to 600MB/s *

Physical Size 4 in; 10.17 cm

Interface Serial ATA (6.0Gb/s), NCQ enabled

Synchronous Transfer

Rate (Maximum)

32MB

Seek Time (typical reads,
includes controller
overhead, includingSingle Track
Average2 ms *11 ms *Full Stroke21 ms *

settling)

Buffer

Rotational Speed 7,200 rpm **Logical Blocks** 976,773,168

Operating Temperature 41° to 131° F (5° to 55° C)

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

1TB SATA 7200	rpm
6Gb/s 3.5" HDD	

Capacity	1TB
Protocol	SATA
Form Factor	3.5"
Controller	AHCI
Height	1 in; 2.54 cm

Width Media Diameter 3.5 in; 8.9 cm
Physical Size 4 in; 10.17 cm

Up to 600 MB/s *

Interface Serial ATA (6.0Gb/s), NCQ enabled

Synchronous Transfer

Rate (Maximum)

Buffer 64MB

Seek Time (typical reads, includes controller overhead, including settling)

Single Track 2 ms *

Average 11 ms *

Full Stroke 21 ms *

Rotational Speed 7,200 rpm
Logical Blocks 1,953,525,168

Operating Temperature 41° to 131° F (5° to 55° C)

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

2TB SATA 7200 rpm 6Gb/s 3.5" HDD Capacity2TBProtocolSATAForm Factor3.5"ControllerAHCI



^{*}Actual performance may vary.

^{*}Actual performance may vary.

Technical Specifications - Hard Drives

Annualized Failure Rate

(based on Rated POH) < 0.62% Height 1 in; 2.54 cm

Width **Media Diameter** 3.5 in: 8.9 cm **Physical Size** 4 in: 10.17 cm

Interface Serial ATA (6.0 Gb/s), NCQ Enabled

Synchronous Transfer

Rate (Maximum)

Up to 600MB/s *

Buffer 64MB

Seek Time (typical reads, **Single Track** 2.0 ms * includes controller 11 ms * Average overhead, including **Full Stroke** 21 ms * settling)

Rotational Speed 7,200 rpm **Logical Blocks** 3,907,029,168

Operating Temperature 41° to 131° F (5° to 55° C)

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

1TB SATA 7200 rpm 6Gb/s 3.5" HDD (Enterprise Class)

Capacity 1TB Height 1 in; 2.54 cm **Protocol** SATA **Form Factor** 3.5" **Controller AHCI** Reliability 2.0M hours **Rated Power On Hours** 8760/vr

Annualized Failure Rate

(based on Rated POH) <0.62%

Width **Media Diameter** 3.5 in: 8.9 cm **Physical Size** 4 in; 10.17 cm

Up to 600MB/s *

Interface Serial ATA (6.0 Gb/s), NCQ Enabled

Synchronous Transfer

Rate (Maximum)

Buffer 128MB

Seek Time (typical reads. Single Track 0.32ms* includes controller **Average** 7.45ms* overhead, including **Full Stroke** 14.2ms* settling)

Rotational Speed 7,200 rpm

Operating Temperature 41° to 140° F (5° to 60° C)

Performance Sequential Read up to 226MB/s*

Sequential Write up to 226MB/s*

Enterprise Class Features High Reliability

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

> Capacity 2TB



^{*}Actual performance may vary.

^{*}Actual performance may vary.

Technical Specifications - Hard Drives

Protocol SATA
Form Factor 3.5"
Controller AHCI
Reliability (MTBF) 2.0M hours
Rated Power On Hours 8760/yr
Annualized Failure Rate <0.62%

(based on Rated POH)

Rated for 24/7/365

Operation

Physical Size (Height)1 in; 2.54 cmPhysical Size (Width)4 in; 10.17 cmMedia Diameter3.5 in; 8.9 cm

Interface Serial ATA (6Gb/s), NCQ enabled

Synchronous Transfer Up to 600MB/s*

Rate (Maximum)

Buffer 128MB

Seek Time (typical reads,
includes controller
overhead, including
settling)Single Track
Average0.7ms*Average
Full Stroke8.5ms*15.7ms*

Rotational Speed 7,200 rpm

Operating Temperature 41° to 131° F (5° to 55° C)

Performance Sequential Read up to 226MB/s*

Sequential Write up to 226MB/s*

Enterprise Class Features High Reliability

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

4TB SATA 7200 rpm 6Gb/s 3.5" HDD (Enterprise Class)

2TB SATA 7200 rpm

6Gb/s 3.5" HDD

(Enterprise Class)

Capacity 4TB
Protocol SATA
Form Factor 3.5"
Controller AHCI
Reliability 2.0M hours
Rated Power On Hours 8760/yr
Annualized Failure Rate <0.62%

(based on Rated POH)
Rated for 24/7/365

Operation

Physical Size (Height)1 in; 2.54 cmPhysical Size (Width)4 in; 10.17 cmMedia Diameter3.5 in; 8.9 cmPhysical Size4 in; 10.17 cm

Interface Serial ATA (6Gb/s), NCQ enabled

Up to 600MB/s*

Synchronous Transfer

Rate (Maximum)

Buffer 256MB



^{*}Actual performance may vary.

Seek Time (typical reads,
includes controller
overhead, including
settling)Single Track
Average0.7ms*Average
Full Stroke8.5ms*15.7ms*

Rotational Speed 7,200 rpm

Operating Temperature 41° to 131° F (5° to 55° C)

Performance Sequential Read up to 226MB/s*
Sequential Write up to 226MB/s*

Enterprise Class Features High Reliability

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

8TB SATA 7200 rpm
6Gb/s 3.5" HDD
(Enterprise Class)

Capacity	8TB
Protocol	SATA
Form Factor	3.5"
Controller	AHCI
Reliability	2.0M hours

WidthMedia Diameter3.5 in; 8.9 cmPhysical Size4 in; 10.17 cm

Up to 600MB/s [1]

Interface Serial ATA (6.0Gb/s), NCQ enabled

Synchronous Transfer

Rate (Maximum)

Buffer 256MB

Seek Time (typical reads,
includes controller
overhead, including
settling)Single Track
Average
Full Stroke0.7ms*
8.5ms*Full Stroke15.7ms*

Rotational Speed 7,200 rpm

Operating Temperature 41° to 140° F (5° to 60° C)

Performance Sequential Read up to 226MB/s¹
Sequential Write up to 226MB/s¹

Enterprise Class Features High Reliability

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

500GB SATA 7.2K SI	ΞD
2.5" HDD	

Capacity	500GB
Protocol	SATA
Form Factor	2.5"

Height 0.275 in; 0.7 cm

Width Media Diameter 2.5 in; 6.36 cm
Physical Size 2.75 in: 6.99 cm

Interface Serial ATA (6.0Gb/s), NCQ enabled

Synchronous Transfer Up to 600MB/s*

Rate (Maximum)

Buffer 64MB

Single Track 1ms*



^{*}Actual performance may vary.

^{*}Actual performance may vary.

25ms (Typical)*

Technical Specifications - Hard Drives

Seek Time (typical reads, Average 4.2ms*

Full Stroke

includes controller overhead, including

settling)

Rotational Speed 7,200 rpm

Operating Temperature 32° to 131° F (0° to 60° C)

Self-Encrypting Drive Yes

Support

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

HP Z Turbo Drv PCIE-4X4 Capacity 512GB TLC PCIe SSD Protocol (Z2G9) _ _ _

Capacity512GBProtocolPCIe

Form Factor M.2 in native Slot on motherboard

Controller NVMe NAND Type 3D TLC

Endurance 150TBW (TB Written)

Reliability (MTBF) 1.5M hours

InterfacePCI Express 4.0 x4 electricalOperating Temperature32° to 178° F (0° to 81° C)

Performance Sequential Read 6400MB/s*

Sequential Write 3400MB/s*
Random Read 600K IOPS*
Random Write 600K IOPS*

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

HP Z Turbo Drv PCIE-4X4 Capacity
1TB TLC PCIe SSD (Z2G9) Protocol

Capacity 1TB Protocol PCIe

Form Factor M.2 in native Slot on motherboard

Controller NVMe
NAND Type 3D TLC

Endurance 300TBW (TB Written)

Reliability 1.5M Hours

Interface PCI Express 4.0 x4 electrical Operating Temperature 32° to 178° F (0° to 81° C)

Performance Sequential Read 6500MB/s*

Sequential Write 5000MB/s*
Random Read 800K IOPS*
Random Write 800K IOPS*

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

Capacity 2TB



^{*}Actual performance may vary.

^{*}Actual performance may vary.

^{*}Actual performance may vary.

Protocol PCle

Form Factor M.2 in native Slot on motherboard

Controller NVMe
NAND Type 3D TLC

Endurance 500TBW (TB Written)

HP Z Turbo Drv PCIE-4X4 Reliability
2TB TLC PCIe SSD (Z2G9) Interface

Reliability 1.5M Hours
Interface PCI Express 4.0 x4 electrical

Operating Temperature 32° to 178° F (0° to 81° C)

Performance Sequential Read 6500MB/s*

Sequential Write 5000MB/s*
Random Read 800K IOPS*
Random Write 800K IOPS*

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

HP Z Turbo Drv PCIE-4X4 Capacity

4TB

TLC PCIe SSD

Capacity 4TB
Protocol PCIe

Form Factor M.2 in native Slot on motherboard

Controller NVMe
NAND Type 3D TLC

Endurance 600TBW (TB Written)

Reliability (MTBF) 1.5M Hours

Interface PCI Express 4.0 x4 electrical
Operating Temperature 32° to 178° F (0° to 81° C)

Performance Sequential Read 6500MB/s*

Sequential Write 5000MB/s*
Random Read 700K IOPS*
Random Write 700K IOPS*

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

HP Z Turbo Drv PCIE Gen4x4 4TB

TLC PCIe SED OPAL2

Capacity 4TB Protocol PCIe

Form Factor M.2 in native Slot on motherboard

Controller NVMe NAND Type 3D TLC

Endurance600TBW (TB Written)InterfacePCI Express 4.0 x4 electricalOperating Temperature32° to 178° F (0° to 81° C)

Performance Sequential Read 6500MB/s*

Sequential Write 5000MB/s*
Random Read 700K IOPS*
Random Write 700K IOPS*



^{*}Actual performance may vary.

^{*}Actual performance may vary.

Self-Encrypting Drive

Support

OPAL2

*Actual performance may vary.

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

HP Z Turbo Drv 512GB TLC PCIe SED OPAL2 (Z2G9) Capacity 512GB Protocol PCle

Form Factor M.2 in native Slot on motherboard

Controller NVMe NAND Type 3D TLC

Endurance 150TBW (TB Written)

Reliability 1.5M Hours

Interface PCI Express 4.0 x4 electrical **Operating Temperature** 32° to 178° F (0° to 81° C)

Performance Sequential Read 6400MB/s*
Sequential Write 3400MB/s*

Random Read 600K IOPS* Random Write 600K IOPS*

Self-Encrypting Drive OPAL2

Support

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

HP Z Turbo Drv 1TB
TLC PCIe SED
OPAL2 (Z2G9)

Capacity 1TB Protocol PCle

Form Factor M.2 in native Slot on motherboard

Controller NVMe NAND Type 3D TLC

Endurance 300TBW (TB Written)

Reliability 1.5M Hours

InterfacePCI Express 4.0 x4 electricalOperating Temperature32° to 178° F (0° to 81° C)

Performance Sequential Read 6500MB/s*

Sequential Write 5000MB/s*
Random Read 800K IOPS*
Random Write 800K IOPS*

Self-Encrypting Drive 0

Support

OPAL2

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

HP Z Turbo Drv 2TB TLC PCIe SED OPAL2 (Z2G9) Capacity 2TB Protocol PCIe

Form Factor M.2 in native Slot on motherboard

^{*}Actual performance may vary.

^{*}Actual performance may vary.

Controller NVMe NAND Type 3D TLC

Endurance 500TBW (TB Written)

Reliability 1.5M Hours

Interface PCI Express 4.0 x4 electrical Operating Temperature 32° to 178° F (0° to 81° C)

Performance Sequential Read 6500MB/s*

Sequential Write 5000MB/s*
Random Read 800K IOPS*
Random Write 800K IOPS*

Self-Encrypting Drive OPAL2

Support

*Actual performance may vary.

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

256GB 2280 PCIe-4x4 Value M.2 SSD **Capacity** 256GB **Protocol** PCIe

Form Factor M.2 in native Slot on motherboard

Controller NVMe
NAND Type 3D TLC

Endurance 150TBW (TB Written)

Reliability 1.5M Hours

Interface PCI Express 4.0 x4 electrical Operating Temperature 32° to 158° F (0° to 70° C)

Performance Sequential Read 3100MB/s*

Sequential Write 1400MB/s*
Random Read 200K IOPS*
Random Write 400K IOPS*

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

512GB 2280 PCIe-4x4 Value M.2 SSD Capacity 512GB Protocol PCle

Form Factor M.2 in native Slot on motherboard

Controller NVMe NAND Type 3D TLC

Endurance 300TBW (TB Written)

Reliability 1.5M Hours

Interface PCI Express 4.0 x4 electrical Operating Temperature 32° to 158° F (0° to 70° C)

Performance Sequential Read 3400MB/s*

Sequential Write 2500MB/s*
Random Read 380K IOPS*
Random Write 430K IOPS*



^{*}Actual performance may vary.

Technical Specifications - Hard Drives

*Actual performance may vary.

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

1TB 2280 PCIe-4x4 ValueCapacity1TBM.2 SSDProtocolPCIe

Form Factor M.2 in native Slot on motherboard

Controller NVMe NAND Type 3D TLC

Endurance 400TBW (TB Written)

Reliability 1.5M Hours

Interface PCI Express 4.0 x4 electrical
Operating Temperature 32° to 158° F (0° to 70° C)

Performance Sequential Read 3400MB/s*

Sequential Write 2500MB/s*
Random Read 500K IOPS*
Random Write 440K IOPS*

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.



^{*}Actual performance may vary.

Technical Specifications - Graphics

AMD Radeon™ Pro W6600 8GB Graphics **Form Factor** Single slot, full-height, 9.5" length

Graphics Controller Navi23 architecture

Power: 122 Watts

Cooling Solution: Active Fan Heatsink

Bus TypePCI Express 4.0 x8Memory8GB GDDR6 Memory

Memory Bandwidth: 224 GB/s Memory Interface: 128 bit

Connectors 4x DisplayPort™ 1.4 with DSC

- HDR Ready

Supports Multi-Stream Transport (MST)

Max simultaneous

displavs

@ 60Hz with HDR Enabled 4x @ 3840x2160px (4K) 4x @ 5120x2880px (5K) 1x @ 7680x4320px (8K)

DirectX 12 Shader Model 6.5

Shading Architecture

Supported Graphics APIs

DirectX®12 Ultimate

OpenGL® 4.6 OpenCL™ 2.1 Vulkan™ 1.2

Available Graphics Drivers Windows 10 64-bit Windows 11 64-bit

Linux® 64-bit (selected Enterprise distributions)

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html

AMD Radeon™ Pro W6800 Form Factor

32GB Graphics

Double slot, full-height, 10.5" length

Graphics Controller Navi21 architecture

Power: 261 Watts

Cooling Solution: Active Fan Heatsink

Bus Type PCI Express 4.0 x16 **Memory** 8GB GDDR6 Memory

Memory Bandwidth: 512 GB/s Memory Interface: 256 bit

Connectors 6x Mini-DisplayPort™ 1.4 with DSC

- HDR Ready

- Supports Multi-Stream Transport (MST)

Max simultaneous

displays

@ 60Hz with HDR Enabled 6x @ 3840x2160px (4K) 6x @ 5120x2880px (5K)

2x @ 7680x4320px (8K)

Shading Architecture

DirectX 12 Shader Model 6.5

Supported Graphics APIs DirectX®12 Ultimate

OpenGL® 4.6 OpenCL™ 2.1 Vulkan™ 1.2



Technical Specifications - Graphics

NVIDIA® T400 4GB Graphics Form Factor Single Slot, Low Profile (2.7" H x 6.1" L)

Graphics Controller Turing architecture

Max Power: 30 Watts

Cooling Solution: Active fan heatsink

Bus TypePCI Express 3.0 x16Memory4GB GDDR6 Memory

Memory Bandwidth: 80 GB/s Memory Interface: 64 bit

Connectors 3x mDP (Mini DisplayPort[™]) 1.4 Connectors

Max simultaneous

displays - 3x 3840 x 2160 @ 120Hz

- 3x 5120 x 2880 @ 60Hz

- supports Multi-Stream Transport (MST)

Shading Architecture DirectX 12 Shader Model 5.1

Supported Graphics APIs OpenGL 4.6

DirectX 12 Vulkan 1.2

API support includes: CUDA, OpenCL 1.2 Windows 10 64-bit

Available Graphics

Drivers

Windows 10 64-bit

Linux® 64-bit (selected Enterprise distributions)

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html

NVIDIA® T600 4GB Graphics* Form Factor Single Slot, Low Profile (2.7" H x 6.1" L)

Graphics Controller Turing architecture Max Power: 40 Watts

Cooling Solution: Active fan heatsink

Bus Type PCI Express 3.0 x16 **Memory** 4GB GDDR6 Memory

Memory Bandwidth: 160 GB/s Memory Interface: 128 bit

Connectors 4x mDP (Mini DisplayPort™) 1.4 Connectors

 Max simultaneous
 - 4x 3840 x 2160 @ 120Hz

 displays
 - 4x 5120 x 2880 @ 60Hz

- 2x 7680 x 4320 @ 60Hz

- supports Multi-Stream Transport (MST)

Shading Architecture DirectX 12 Shader Model 5.1

Supported Graphics APIs OpenGL 4.6

DirectX 12 Vulkan 1.2

API support includes: CUDA, OpenCL 1.2 Windows 10 64-bit

Available Graphics Windows 10 64-bit **Drivers** Windows 11 64-bit

Linux® 64-bit (selected Enterprise distributions)

Technical Specifications - Graphics

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html

*May go End of Life in late 2022

AMD® Radeon™ RX 6400 4GB Graphics **Form Factor** Single slot, Low Profile (2.8" H x

6.3" L)

Weight: 155g

Graphics Controller Radeon™ RX 6400

Max Power: 53W

Cooling Solution: Active axial fan

Architecture: RDNA™ 2

Bus TypePCI Express x4 Gen4MemorySize: 4GB GDDR6

Interface: 64-bit

Bandwidth: up to 128 GB/s

 Connectors
 DP (DisplayPort™) 1.4 + HDMI 2.1

 Max simultaneous
 - up to 4x 5120 x 2880 x 24 bpp @

displays

60Hz

Shading Architecture

Microsoft DirectX 12 Shader Model

5.1

Supported Graphics APIs OpenGL® 4.6

DirectX® 12 Ultimate

Vulkan™ 1.1

API support includes: OpenCL™ 2.2

Available Graphics

Drivers

Microsoft Windows 10 64-bit, Windows 11 64-bit

HP qualified drivers may be preloaded or the latest prosumer graphics

drivers are available from the AMD.com

Notes This is a Prosumer or Consumer graphics card, and not a Professional

graphics card. As such, it does not have formal professional application validation, but is intended per AMD to function properly for game development, real-time engine, and many prosumer application workloads. Customers using Prosumer or Consumer graphic cards with axial fan cooling solutions are likely to experience higher acoustics in comparison with Professional graphic cards that use blower fan cooling.

NVIDIA® T1000 4GB Graphics

Form Factor Single Slot, Low Profile (2.7" H x

6.1" L)

Graphics Controller Turing architecture

Max Power: 50 Watts

Cooling Solution: Active fan heatsink

Bus Type PCI Express 3.0 x16 **Memory** 4GB GDDR6 Memory

Memory Bandwidth: 160 GB/s Memory Interface: 128 bit

Connectors 4x mDP (Mini DisplayPort™) 1.4 Connectors

Technical Specifications - Graphics

Max simultaneous

displays

- 4x 3840 x 2160 @ 120Hz - 4x 5120 x 2880 @ 60Hz

- 2x 7680 x 4320 @ 60Hz

- supports Multi-Stream Transport (MST)

Shading Architecture

DirectX 12 Shader Model 5.1

Supported Graphics APIs

OpenGL 4.6 DirectX 12 Vulkan 1.2

API support includes: CUDA, OpenCL 1.2 Windows 10 64-bit

Available Graphics

Drivers

Windows 10 64-bit Windows 11 64-bit

Linux® 64-bit (selected Enterprise distributions)

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html

NVIDIA® T1000 8GB Graphics

Form Factor

Single Slot, Low Profile (2.7" H x

6.1" L)

Graphics Controller

Turing architecture Max Power: 50 Watts

Cooling Solution: Active fan heatsink

Bus Type Memory PCI Express 3.0 x16 8GB GDDR6 Memory

Memory Bandwidth: 160 GB/s Memory Interface: 128 bit

Connectors

4x mDP (Mini DisplayPort™) 1.4 Connectors

Max simultaneous

displays

- 4x 3840 x 2160 @ 120Hz - 4x 5120 x 2880 @ 60Hz - 2x 7680 x 4320 @ 60Hz

- supports Multi-Stream Transport (MST)

Shading Architecture

DirectX 12 Shader Model 5.1

Supported Graphics APIs

OpenGL 4.6 DirectX 12 Vulkan 1.2

API support includes: CUDA, OpenCL 1.2 Windows 10.64-bit

Available Graphics

Drivers

Windows 10 64-bit Windows 11 64-bit

Linux® 64-bit (selected Enterprise distributions)

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html

NVIDIA® RTX™ A2000 12GB Graphics **Form Factor**

Low-Profile Double Slot (2.7" H x

6.1" L)

Graphics Controller

Ampere architecture Power: 70 Watts

Cooling: Active Fan Heatsink

Technical Specifications - Graphics

Bus Type PCI Express 4.0 x16 **Memory** 12GB GDDR6 memory

Memory Bandwidth: 288 GB/s Memory Interface: 192 bit

Support Error-correcting code (ECC)

Connectors 4x mDP (Mini DisplayPort™) 1.4 Connectors

 Max simultaneous
 4x 4096 x 2160 @ 120 Hz,

 displays
 4x 5120 x 2880 @ 60 Hz

 2x 7680 x 4320 @ 60 Hz

Shading Architecture Shader Model 6.5

Supported Graphics APIs OpenGL 4.6 DirectX 12

Vulkan 1.2 API support includes: CUDA, OpenCL 1.2

Available Graphics Windows 10 64-bit Windows 11 64-bit

Linux® 64-bit (selected Enterprise distributions)

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html

NVIDIA® RTX™ A4000 16GB Graphics **Form Factor** Full Height Single Slot (9.5"

Length)

Graphics Controller Ampere architecture

Power: 140 Watts

Cooling: Active Fan Heatsink

Bus TypePCI Express 4.0 x16Memory16GB GDDR6 memory

Memory Bandwidth: 448 GB/s Memory Interface: 256 bit

Support Error-correcting code (ECC)

 Connectors
 4x DP 1.4 Connectors

 Max simultaneous displays
 4x 4096 x 2160 @ 120 Hz, 4x 5120 x 2880 @ 60 Hz, 2x 7600 x 4220 @ 60 Hz

2x 7680 x 4320 @ 60 Hz

Shading Architecture Shader Model 6.5 **Supported Graphics APIs** OpenGL 4.6

DirectX 12 Vulkan 1.2

API support includes: CUDA, OpenCL 1.2 Windows 10 64-bit

Available Graphics Windows 10 64-bit Windows 11 64-bit

Linux® 64-bit (selected Enterprise distributions)

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html



Technical Specifications - Graphics

NVIDIA® RTX™ A4500 20GB Graphics Form Factor Full Height Double Slot (10.5"

Length)

Graphics Controller Ampere architecture

Power: 200 Watts

Cooling: Active Fan Heatsink

Bus Type PCI Express 4.0 x16
Memory 20GB GDDR6 memory

Memory Bandwidth: 640 GB/s Memory Interface: 320 bit

Support Error-correcting code (ECC)

 Connectors
 4x DP 1.4 Connectors

 Max simultaneous displays
 4x 4096 x 2160 @ 120 Hz, 4x 5120 x 2880 @ 60 Hz,

2x 7680 x 4320 @ 60 Hz

Shading Architecture Shader Model 6.5

Supported Graphics APIs OpenGL 4.6

DirectX 12 Vulkan 1.2

API support includes: CUDA, OpenCL 1.2 Windows 10 64-bit

Available Graphics

Drivers

Windows 10 64-bit Windows 11 64-bit

Linux® 64-bit (selected Enterprise distributions)

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html

NVIDIA® RTX™ A5000 24GB Graphics Form Factor Full Height Double Slot (10.5"

Length)

Graphics Controller Ampere architecture

Power: 230 Watts

Cooling: Active Fan Heatsink

Bus Type PCI Express 4.0 x16 **Memory** 24GB GDDR6 memory

Memory Bandwidth: 768 GB/s Memory Interface: 384 bit

Support Error-correcting code (ECC)

 Connectors
 4x DP 1.4 Connectors

 Max simultaneous
 4x 4096 x 2160 @ 120 Hz,

 displays
 4x 5120 x 2880 @ 60 Hz,

2x 7680 x 4320 @ 60 Hz

Shading Architecture Shader Model 6.5 Supported Graphics APIs OpenGL 4.6

> DirectX 12 Vulkan 1.2

API support includes: CUDA, OpenCL 1.2 Windows 10 64-bit

Available Graphics Windows 10 64-bit Drivers Windows 11 64-bit

Linux® 64-bit (selected Enterprise distributions)

Technical Specifications - Graphics

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html

AMD Radeon™ RX 6700 XT Form Factor Dual slot, Full Length (254mm L x

38mm W x 108.65mm H)

Graphics Controller AMD Radeon™ RX 6700 XT Graphics

GPU: 2560 Navi2 Stream Processors

Memory: 12GB GDDR6

Power: 230 Watts, Standard graphics 8pin + 6pin auxiliary power

Cooling: Active, Dual Axial fan

Bus Type PCI Express 4.0 x16

Connectors3DP 1.4 + HDMI 2.1 OutputsMaximum ResolutionDisplayPort™ 1.4 with DSC:

- up to 4x 5210 x 3200 x 24 bpp @ 60Hz, uncompressed

- up to 7680 x 4320, compressed Display Outputs 3 DP + 1 HMDI

Shading Architecture Microsoft DirectX 12 Shader Model 6.1

Supported Graphics APIs OpenGL 4.6

DirectX 12 Feature Level 12_1

Vulkan 1.1 OpenCL 2.2

Available Graphics Windows 11

Drivers Linux® 64-bit (selected distributions)

Typically, latest drivers will be available from amd.com

Notes: This is a Prosumer or Consumer graphics card, and not a Professional graphics card. As such, it does not have formal professional application validation, but is intended per AMD to function properly for game development, real-time engine, and many prosumer application workloads. Customers using Prosumer or Consumer graphic cards are likely to experience higher acoustics in comparison with Professional graphic cards. The higher acoustics observed with non-professional graphics is expected, as HP Workstations' designs do not have control in this area.

HP 9.5mm Slim DVD Writer

Description 9.5mm height, tray-load

Mounting Orientation Either horizontal or vertical

Interface Type SATA/ATAPI

Dimensions (WxHxD) 128 x 9.5 x 127mm

Supported Media Types DVD+R

DVD+RW
DVD+R DL
DVD-R DL
DVD-R
DVD-RW
CD-R
CD-RW

Disc Capacity DVD-ROM 8.5 GB DL or 4.7 GB standard

Access Times Full Stroke DVD < 200 ms (seek)

Full Stroke CD < 200 ms (seek)

CD ROM Read CD-ROM, CD-R Up to 24X



Technical Specifications - Graphics

Maximum Data Transfer CD-RW Up to 24X

Rates

DVD ROM Read DVD+RW Up to 8X

DVD-RW Up to 8X DVD+R DL Up to 8X DVD-R DL Up to 8X DVD-ROM Up to 8X DVD-ROM DL Up to 8X DVD+R Up to 8X DVD-R Up to 8X

Power SATA DC power receptacle Source

> **DC Power Requirements** 5 VDC ± 5%-100 mV ripple p-p

DC Current 5 VDC -< 800 mA typical, <1600 mA maximum

Operating Environmental Temperature 41° to 122° F (5° to 50° C)

(all conditions non-

Relative Humidity 10% to 80% condensing) **Maximum Wet Bulb** 84° F (29° C)

Temperature

Operating Systems

Windows 11, Windows 10, Windows 7 Professional 64-bit, Supported

Windows Vista Business 64*, Windows 2000.

Linux®.

Kit Contents HP SATA DVD Writer drive, installation guide.

USB-IF, WHQL, Compliant with USB Mass Storage Class Bulk only Transport **Approvals**

Specification Rev. 1.0.

Compliant Intel Front Panel I/O Connectivity Design Guide V. 1.3, FCC, CE,

BSMI, C-Tick, VCCI, MIC, cUL, TUVT

NOTE: Actual speeds may vary. No support for DVD-RAM (DVD Writer). Does not permit copying of commercially available DVD movies or other copyright protected materials. Intended for creation and storage of your original material and other lawful uses. Double Layer discs can store more data than single layer discs. However, double-layer discs burned with this drive may not be compatible with many existing single-layer DVD drives and players.

HP 9.5mm Slim DVD-ROM Description Drive

9.5mm height, tray-load **Mounting Orientation** Either horizontal or vertical

Interface Type SATA / ATAPI **Dimensions** (WxHxD) 128 x 9.5 x 127mm

Disc Capacity DVD-ROM Single layer: Up to 4.7 GB

Double layer: Up to 8.5 GB

Access Times DVD-ROM Single Layer < 110 ms (typical)

> **CD-ROM Mode 1** < 110 ms (typical) **Full Stroke DVD** < 230 ms (typical) **Full Stroke CD** < 220 ms (typical)

Power Source SATA DC power receptacle

> **DC Power Requirements** 5 VDC ± 5%-100 mV ripple p-p

5 VDC - <800mA typical, < 1600 mA maximum **DC Current**

41° to 122° F (5° to 50° C) **Temperature**

Technical Specifications - Graphics

Operating Environmental
(all conditions non-
condensing)Relative Humidity10% to 80%Maximum Wet Bulb
Temperature84° F (29° C)

Operating Systems

Supported

Windows 11, Windows 10, Windows 7 Professional 64-bit,

Windows Vista Business 64*, Windows 2000.

Linux®.

Kit Contents 9.5mm Slim DVD-ROM Drive, slim SATA data/power cable, installation

guide

Approvals USB-IF, WHQL, Compliant with USB Mass Storage Class Bulk only Transport

Specification Rev. 1.0,

Compliant Intel Front Panel I/O Connectivity Design Guide V. 1.3, FCC, CE,

BSMI, C-Tick, VCCI, MIC, cUL, TUVT

NOTE: Actual speeds may vary. No support for DVD-RAM (DVD Writer). Does not permit copying of commercially available DVD movies or other copyright protected materials. Intended for creation and storage of your original material and other lawful uses. Double Layer discs can store more data than single layer discs. However, double-layer discs burned with this drive may not be compatible with many existing single-layer DVD drives and players.



Technical Specifications - Networking and Communications

Integrated Intel® I219LM Connector

PCIe GbE Controller (Intel® vPro® with Intel® AMT 16.01) Connector RJ-45

Cabling Twisted pair up to 100m

Controller Intel® I219LM GbE platform LAN connect networking controller

Memory 3 KB Tx and 3KB Rx FIFO packet buffer memory

Data Rates Supported 10/100/1000 Mbps

Compliance 802.1as/1588, 802.1p, 802.1Q, 802.3, 802.3ab, 802.3az, 802.3i, 802.3u,

802.3z

Bus Architecture PCI Express and SMBus

Data Transfer Mode PCIe-based interface for active state operation (S0 state) and SMBus for

host and management traffic (Sx low power state)

Power Requirement Requires 3.3V (integrated regulators for core Vdc)

Boot ROM Support Yes

Network Transfer Mode Full-duplex; Half-duplex

Network Transfer Rate 10BASE-T (half-duplex) 10 Mbps

10BASE-T (full-duplex) 20 Mbps 100BASE-TX (half-duplex) 100 Mbps 100BASE-TX (full-duplex) 200 Mbps 1000BASE-T (full-duplex) 2000 Mbps

Management Capabilities vPro®, WOL, auto MDI crossover, PXE, Muti-port teaming, RSS, ACPI,

Advanced cable diagnostic, loopback modes,

AMT 16.0 support, Circuit Breaker, VLAN, Multicast Listener Discovery

(MLD)

¹Requires activation and a system with a corporate network connection, an Intel® AMT enabled chipset, and network hardware and software. For notebooks, Intel AMT may be unavailable or limited over a host OS-based VPN, when connecting wirelessly, on battery power, sleeping, hibernating, or powered off. Results dependent upon hardware, setup, and configuration. For more information, visit: https://www.intel.com/content/www/us/en/architecture-and-technology/intel-active-management-technology.html

HP 1-Port 1GbE Flex IO NIC

Connector RJ-45

Cabling 1GbE over Category 5e (or better) up to 100m

ControllerRealtek RTL8153Data Rates Supported10/100/1000 Mbps

Compliance 802.3 (LAN)

802.3u (100BASE-TX) 802.3ab (1000BASE-T) 802.3x (Ethernet Flow Control)

802.1Q (Virtual LAN)

802.3az (Energy Efficient Ethernet)

Bus Architecture USB

Power Requirement Requires 3.3V (integrated regulators for core Vdc)

Boot ROM Support Yes

Network Transfer Mode Full-duplex; Half-duplex

Network Transfer Rate 10BASE-T (half-duplex) 10 Mbps

10BASE-T (full-duplex) 20 Mbps 100BASE-TX (half-duplex) 100 Mbps

Technical Specifications - Networking and Communications

100BASE-TX (full-duplex) 200 Mbps 1000BASE-T (full-duplex) 2000 Mbps

Operating Temperature

32° to 131° F (0° to 55° C)

Dimensions (HxW)

1.5 in x 1.5 in. x 0.75 in (3.81 cm x 3.81 cm x 1.9 cm)

Operating System Driver Windows 11 64-bit

Support

Windows 10 64-bit

Linux®

Intel® X550-T2 2-Port **10GbE NIC**

Connector Dual-port RJ-45

Cabling 10GbE: Cat6a (or better) up to 100m

5GbE and below: Cat5e (or better) up to 100m

Controller Intel® Ethernet Controller X550

Network Transfer Rates

10GbE, 5GbE, 2.5GbE, 1GbE, 100MbE

Supported

Data Path Width PCIe Gen3x4

Power Requirement 11.2W (typical) 13.0 (Maximum)

Operating Temperature 32° to 131° F (0° to 55° C) Dimensions (HxW)

5.1 x 2.7 in (without brackets)

Operating System Driver Windows 11 64-Bit

Support

Windows 10 64-bit

Linux®

Kit Contents • Intel® X550-T2 2-Port 10GbE NIC with standard height bracket

attached

 Low-profile bracket Product Literature

Intel® I350-T4 4-Port 1GbE NIC

Connector 4 RJ-45

Cabling Cat5e (or better) up to 100m Controller Intel® Ethernet I350 Controller

Network Transfer Rates

Supported

1GbE, 100MbE, 10MbE

Data Path Width PCIe Gen2.1x4 **Power Requirement** 5W (typical)

Operating Temperature 32° to 131° F (0° to 55° C)

Dimensions (HxW) 2.75 x 5.5 inches (without brackets)

Operating System Driver Windows 11

Support

Windows 10

Linux®

Kit Contents Intel® 1350-T4 4-Port 1GbE NIC with standard height bracket attached

Low-profile bracket

Product Literature

HP Flex 1GbE Fiber LC Single Port

Connector Fiber

Cabling 1GbE over Category OM1 (or better) up to 100m

Microchip LAN7801 Controller

Technical Specifications - Networking and Communications

Data Rates Supported

100/1000 Mbps

Compliance

IEEE 802.1p priority encoding/tagging (QoS, CoS)

IEEE 802.1q VLAN tagging IEEE 802.3x flow control

Bus Architecture USB

Power Requirement

Requires 3.3V (integrated regulators for core Vdc)

Boot ROM Support

Network Transfer Mode Full-duplex; Half-duplex

Network Transfer Rate 100BASE-X (half-duplex) 100 Mbps

> 1000BASE-X (half-duplex) 1000 Mbps 1000BASE-X (full-duplex) 2000 Mbps

Operating Temperature

32° to 158° F (0°C to 70°C)

calvin

1.5 in x 1.7 in. x 0.75 in (3.84 cm x 4.3 cm x 1.9 cm)

Operating System Driver Windows 11 64-Bit

Support

Windows 10 64-bit

Linux®

Intel® I225-T1 1-Port 2.5GbE NIC

Connector **RJ-45**

Cat5e (or better) up to 85m Cabling Controller Intel® Ethernet I225 Controller **Network Transfer Rates** 2.5GbE, 1GbE, 100MbE, 10MbE

Supported

PCIe Gen3.1x1

Data Path Width Power Requirement 1.9W (typical)

Operating Temperature 32° to 158° F (0°C to 70°C)

Dimensions (HxW) 2.7 in x 2.57 in. (68.7mm x 65.3mm)

Operating System Driver Windows 11 64-Bit

Windows 10 64-bit

Linux®

Kit Contents Intel® I225-T1 1-Port 2.5GbE NIC with standard height bracket attached

> Low-profile bracket Product Literature

Intel® Wi-Fi 6E* AX211 802.11ax, BT 5.3, M.2 **With Internal Antenna**

WLAN Standards 802.11abgn+acR2+axR2(Pre-Standard) MIMO 2x2

High performance, low power dual band Pre-Standard-802.11ax R2 2x2.

both with 160MHz channel support - Wi-Fi 6E

Antenna 2x2 Dual-Band (internal)

Bluetooth Standards 5.2

Operating Temperature 32° to 176° F (0° to 80° C)

Interface M.2 CNVio2 **Dimensions** M.2 2230 **Kit Contents** Not Available

NOTE: The AX211 with internal antenna only support WIFI 6

*Wi-Fi 6E requires a Wi-Fi 6E router, sold separately, to function in the 6GHz band. Availability of public wireless access points limited. Wi-Fi 6E is backwards compatible with prior 802.11 specs. And available in countries where Wi-Fi 6E is supported.

Technical Specifications - Networking and Communications

Intel® Wi-Fi 6E* AX211 802.11ax, BT 5.3, M.2 With External Antenna WLAN Standards 802.11abgn+acR2+axR2(Pre-Standard) MIMO 2x2

High performance, low power dual band Pre-Standard-802.11ax R2 2x2,

both with 160MHz channel support – Wi-Fi 6E

Antenna 2x2 Dual-Band (External)

Bluetooth Standards 5.2

Operating Temperature 32° to 176° F (0° to 80° C)

InterfaceM.2 CNVio2DimensionsM.2 2230

Kit Contents ANTENNA, External, Dipole, WLAN, WIFI 6E

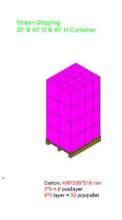
NOTE: The AX211 with external antenna support WIFI 6E

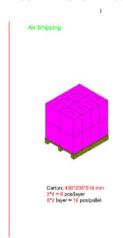
*Wi-Fi 6E requires a Wi-Fi 6E router, sold separately, to function in the 6GHz band. Availability of public wireless access points limited. Wi-Fi 6E is backwards compatible with prior 802.11 specs. And available in countries where Wi-Fi 6E is supported.

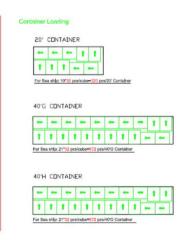
Palletization

Ocean Shipping uses a 20' x 40' x 40' (490mm x 295mm x 518mm) container with 4 layers; 2x4=8 pieces per layer for a total of 32 pieces per pallet

Air shipping uses 490mm x 295mm x 518mm carton with 2 layers; 2x4=8 pieces per layer for a total of 16 pieces per pallet.







Date of change:	Version History:		Description of change:
March 8, 2022	From v1 to v2	Changed	Format
March 16, 2022	From v2 to v3	Changed	Social and Environmental Responsibility section
May 6, 2022	From v3 to v4	Changed	Processors, Graphics, Networking and Communications sections
June 1, 2022	From v4 to v5	Changed	Operating Systems and SATA Hard Drives sections
June 15, 2022	From v5 to v6	Changed	Networking and Communications section
July 1, 2022	From v6 to v7	Changed	Graphics section
July 8, 2022	From v7 to v8	Changed	System Board section
August 1, 2022	From v8 to v9	Changed	SATA Hard Drives, Other Hardware sections
August 4, 2022	From v9 to v10	Changed	Format
September 1, 2022	From v10 to v11	Changed	Storage / Hard Drives, Graphics, Optical and Removable Storage Networking and Communications sections
October 1, 2022	From v11 to v12	Changed	Graphics, Networking and Communications sections
November 1, 2022	From v12 to v13	Changed	Graphics Adapters section
February 6, 2023	From v13 to v14	Changed	Processors section



Technical Specifications - Networking and Communications

March 1, 2023	From v14 to v15	Changed	Manageability section
March 30, 2023	From v15 to v16	Changed	Processors section
April 25, 2023	From v16 to v17	Changed	Power Supply, Social and Environmental Responsibility sections
May 1, 2023	From v17 to v18	Changed	Other Hardware section
June 1, 2023	From v18 to v19	Changed	Graphics, Social and Environmental Responsibility, Palletization sections
July 1, 2023	From v19 to v20	Changed	Networking and Communications, Other Hardware, HP BIOS sections
July 5, 2023	From v20 to v21	Changed	System Board section
August 1, 2023	From v21 to v22	Changed	Social and Environmental Responsibility section
August 1, 2023	From v22 to v23	Changed	ENVIRONMENTAL DATA section
September 15, 2023	From v23 to v24	Changed	Networking and Communications
October 1, 2023	From v24 to v25	Changed	Graphics, Input Devices sections



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